ZL50023 Enhanced 4 K Digital Switch

Data Sheet

Features January 2006

- 4096 channel x 4096 channel non-blocking digital Time Division Multiplex (TDM) switch at 8.192 Mbps and 16.384 Mbps or using a combination of ports running at 2.048 Mbps, 4.096 Mbps, 8.192 Mbps and 16.384 Mbps
- 32 serial TDM input, 32 serial TDM output streams
- Output streams can be configured as bidirectional for connection to backplanes
- Exceptional input clock cycle to cycle variation tolerance (20 ns for all rates)
- Per-stream input and output data rate conversion selection at 2.048 Mbps, 4.096 Mbps 8.192 Mbps or 16.384 Mbps. Input and output data rates can differ
- Per-stream high impedance control outputs (STOHZ) for 16 output streams
- Per-stream input bit delay with flexible sampling point selection

- Ordering Information

 ZL50023GAC 256 Ball PBGA Trays
 ZL50023QCC 256 Lead LQFP Trays
 ZL50023GAG2 256 Ball PBGA** Trays, Bake & Drypack

 **Pb Free Tin/Silver/Copper
 -40°C to +85°C
- Per-stream output bit and fractional bit advancement
- Per-channel ITU-T G.711 PCM A-Law/μ-Law Translation
- Four frame pulse and four reference clock outputs
- Three programmable delayed frame pulse outputs
- Input clock: 4.096 MHz, 8.192 MHz, 16.384 MHz
- Input frame pulses: 61 ns, 122 ns, 244 ns
- Per-channel constant or variable throughput delay for frame integrity and low latency applications

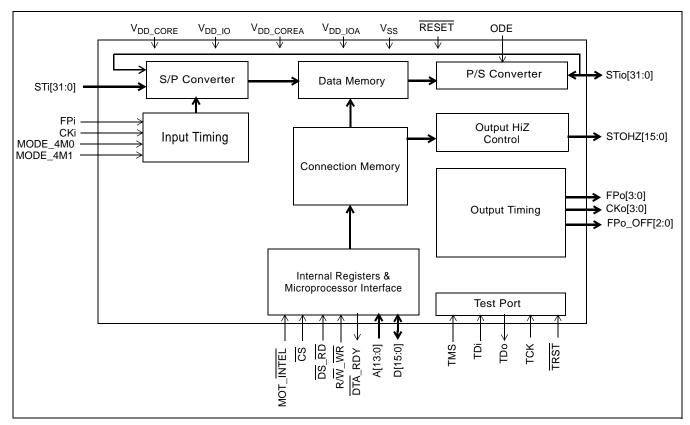


Figure 1 - ZL50023 Functional Block Diagram

- Per Stream (32) Bit Error Rate Test circuits complying to ITU-0.151
- · Per-channel high impedance output control
- Per-channel message mode
- Control interface compatible with Intel and Motorola 16-bit non-multiplexed buses
- · Connection memory block programming
- Supports ST-BUS and GCI-Bus standards for input and output timing
- IEEE-1149.1 (JTAG) test port
- 3.3 V I/O with 5 V tolerant inputs; 1.8 V core voltage

Applications

- PBX and IP-PBX
- Small and medium digital switching platforms
- · Remote access servers and concentrators
- Wireless base stations and controllers
- Multi service access platforms
- Digital Loop Carriers
- Computer Telephony Integration

Description

The ZL50023 is a maximum 4096 x 4096 channel non-blocking digital Time Division Multiplex (TDM) switch. It has thirty-two input streams (STio - 31) and thirty-two output streams (STio0 - 31). The device can switch 64 kbps and Nx64 kbps TDM channels from any input stream to any output stream. Each of the input and output streams can be independently programmed to operate at any of the following data rates: 2.048 Mbps, 4.096 Mbps, 8.192 Mbps or 16.384 Mbps. The ZL50023 provides up to sixteen high impedance control outputs (STOHZ0 - 15) to support the use of external tristate drivers for the first sixteen output streams (STio0 - 15). The output streams can be configured to operate in bi-directional mode, in which case STi0 - 31 will be ignored.

The device contains two types of internal memory - data memory and connection memory. There are four modes of operation - Connection Mode, Message Mode, BER mode and high impedance mode. In Connection Mode, the contents of the connection memory define, for each output stream and channel, the source stream and channel (the actual data to be output is stored in the data memory). In Message Mode, the connection memory is used for the storage of microprocessor data. Using Zarlink's Message Mode capability, microprocessor data can be broadcast to the data output streams on a per-channel basis. This feature is useful for transferring control and status information for external circuits or other TDM devices. In BER mode the output channel data is replaced with a pseudorandom bit sequence (PRBS) from one of 32 PRBS generators that generates a 2¹⁵-1 pattern. On the input side channels can be routed to one of 32 bit error detectors. In high impedance mode the selected output channel can be put into a high impedance state.

The configurable non-multiplexed microprocessor port allows users to program various device operating modes and switching configurations. Users can employ the microprocessor port to perform register read/write, connection memory read/write, and data memory read operations. The port is configurable to interface with either Motorola or Intel-type microprocessors.

The device also supports the mandatory requirements of the IEEE-1149.1 (JTAG) standard via the test port.

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Changes Summary

The following table captures the changes from the October 2004 issue.

Page	Item	Change
31	11.0, "Device Performance Operation in Divided Clock and Multiplied Clock Modes"	Description clarification.
32	11.3, "Output Clock Frequencies"	Added new section to describe output clock frequencies.

1.0 **Pinout Diagrams**

1.1 **BGA Pinout**

•	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	
Α	V _{SS}	STi29	STi28	STi27	STi25	STi26	STi24	NC	NC	STio22	STio23	STio21	STio20	NC	NC	V _{SS}	Α
В	STi31	STi10	STi5	STi4	CKo2	STi0	CKo0	NC	V _{DD} _ COREA	FPi	CKi	IC_Open	IC_Open	IC_GND	ODE	STio19	В
С	STi30	STi9	V _{SS}	STi7	STi6	STi1	CKo1	NC	V _{SS}	IC_Open	IC_Open	IC_Open	IC_GND	V _{SS}	STio15	STio18	С
D	STi17	STi11	V _{DD_IO}	STi3	STi2	NC	NC	NC	NC	V _{SS}	FPo_ OFF1	IC_GND	STio13	V _{DD_IO}	STio14	STio16	D
Е	STi16	STi14	STi8	V _{DD_IO}	V _{SS}	V _{DD} _ CORE	NC	NC	NC	NC	V _{DD} _ CORE	V _{SS}	V _{DD_IO}	STio12	FPo2	STio17	Е
F	STi19	STi15	STi12	STi13	V _{DD_IO}	V _{DD} _ CORE	V _{DD} _ CORE	V _{SS}	V _{SS}	V _{DD} _ CORE	V _{DD} _ CORE	V _{DD_IO}	IC_Open	FPo3	FPo_ OFF2	STOHZ15	F
G	STi18	RESET	IC_GND	IC_Open	TDo	V _{DD_IO}	V_{SS}	V _{SS}	V _{SS}	V _{SS}	V_{DD_IO}	A12	A13	FPo1	FPo0	STOHZ14	G
Н	STi21	V _{SS}	V _{SS}	V _{DD} _ COREA	NC	V _{SS}	V _{SS}	V _{SS}	V _{SS}	V _{SS}	A7	A9	A10	FPo_ OFF0	A11	STOHZ12	Н
J	STi20	V _{DD_IOA}	V _{DD_IOA}	V _{SS}	V _{SS}	CKo3	V_{SS}	V _{SS}	V _{SS}	V _{SS}	А3	A4	A5	A8	A6	STOHZ13	J
K	STi22	V _{SS}	TMS	V _{SS}	V _{DD} _ COREA	V _{DD_IO}	V _{SS}	V _{SS}	V _{SS}	V _{SS}	V _{DD_IO}	IC_Open	A0	A2	A1	STOHZ11	K
L	STi23	V _{DD} _ COREA	TRST	TCK	V _{DD_IO}	V _{DD} _ CORE	V _{DD} _ CORE	V _{SS}	V _{SS}	V _{DD} _ CORE	V _{DD} _ CORE	V _{DD_IO}	STio10	STio11	STio9	STOHZ10	L
М	STio25	NC	TDi	D0	V _{SS}	V _{DD} _ CORE	V _{DD} _ CORE	D6	D10	V _{DD} _ CORE	V _{DD} _ CORE	V _{SS}	MOT_ INTEL	MODE_ 4M0	STio8	STOHZ9	М
N	STio24	NC	V _{DD_IO}	STio0	STOHZ3	D1	D5	D7	D11	D13	R <u>/W</u> _WR	DTA_ RDY	STio4	V _{DD_IO}	STOHZ5	STOHZ8	N
Р	STio26	NC	V _{SS}	STio1	STio3	STOHZ1	D3	D8	D14	NC	STio5	STOHZ4	STOHZ6	V _{SS}	STOHZ7	NC	Р
R	STio27	NC	STOHZ0	STio2	STOHZ2	D2	D4	D9	D12	D15	CS	DS_RD	MODE_ 4M1	STio6	STio7	NC	R
Т	V _{SS}	STio28	STio29	STio31	STio30	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	V _{SS}	Т
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	

Note: A1 corner identified by metallized marking.

Note: Pinout is shown as viewed through top of package.

Figure 2 - ZL50023 256-Ball 17 mm x 17 mm PBGA (as viewed through top of package)

1.2 QFP Pinout

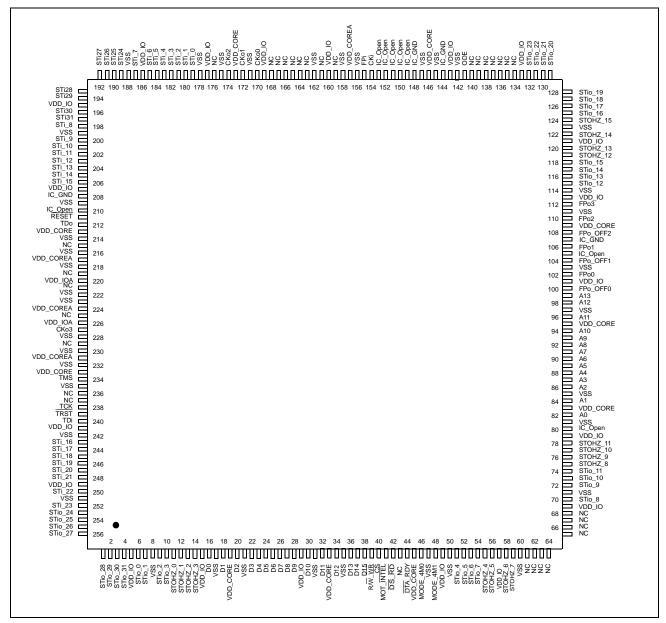


Figure 3 - ZL50023 256-Lead 28 mm x 28 mm LQFP (top view)

2.0 Pin Description

PBGA Pin Number	LQFP Pin Number	Pin Name	Description
E6, E11, F6, F7, F10, F11, L6, L7, L10, L11, M6, M7, M10, M11	19, 33, 45, 83, 95, 109, 146, 173, 213, 233	V _{DD_CORE}	Power Supply for the core logic: +1.8 V
H4, K5, B9, L2	217, 231, 157, 224	V_{DD_COREA}	Power Supply for analog circuitry: +1.8 V
D3, D14, E4, E13, F5, F12, G6, G11, K6, K11, L5, L12, N3, N14	5, 15, 29, 49, 57, 69, 79, 101, 113, 121, 133, 143, 160, 169, 177, 186, 195, 207, 241, 249	V _{DD_IO}	Power Supply for I/O: +3.3 V
J2, J3	220, 226	V_{DD_IOA}	Power Supply for the CKo5 and CKo3 outputs: +3.3 V
A1, A16, C3, C9, C14, D10, E5, E12, F8, F9, G7, G8, G9, G10, H2, H3, H6, H7, H8, H9, H10, J4, J5, J7, J8, J9, J10, K2, K4, K7, K8, K9, K10, L8, L9, M5, M12, P3, P14, T1, T16	8, 17, 21, 31, 35, 47, 50, 60, 71, 81, 85, 97, 103, 111, 114, 123, 142, 145, 147, 156, 158, 162, 171, 175, 178, 188, 199, 209, 214, 216, 218, 222, 223, 228, 230, 232, 235, 242, 251	V _{SS}	Ground

PBGA Pin Number	LQFP Pin Number	Pin Name	Description
К3	234	TMS	Test Mode Select (5 V-Tolerant Input with Internal Pull-up) JTAG signal that controls the state transitions of the TAP controller. This pin is pulled high by an internal pull-up resistor when it is not driven.
L4	238	TCK	Test Clock (5 V-Tolerant Schmitt-Triggered Input with Internal Pull-up) Provides the clock to the JTAG test logic.
L3	239	TRST	Test Reset (5 V-Tolerant Input with Internal Pull-up) Asynchronously initializes the JTAG TAP controller by putting it in the Test-Logic-Reset state. This pin should be pulsed low during power-up to ensure that the device is in the normal functional mode. When JTAG is not being used, this pin should be pulled low during normal operation.
M3	240	TDi	Test Serial Data In (5 V-Tolerant Input with Internal Pull-up) JTAG serial test instructions and data are shifted in on this pin. This pin is pulled high by an internal pull-up resistor when it is not driven.
G5	212	TDo	Test Serial Data Out (5 V-Tolerant Three-state Output) JTAG serial data is output on this pin on the falling edge of TCK. This pin is held in high impedance state when JTAG is not enabled.
B12, B13, C10, C11, F13, G4, K12, C12,	80, 105, 150, 151, 152, 153, 210, 149	IC_Open	Internal Test Mode (5 V-Tolerant Input with Internal Pull-down) These pins may be left unconnected.
G3, D12, B14,C13	144, 107, 148, 208	IC_GND	Internal Test Mode Enable (5 V-Tolerant Input) These pins MUST be low.

PBGA Pin Number	LQFP Pin Number	Pin Name	Description
A8, A9, A14, A15, E10, M2, N2, P2, P16, R2, R16, T6, T7, T8, T9, T10, T11, T12, T13, T14, T15, D9, E8, C8, E7, D6, H5,P10, E9, D8, B8, D7,	61, 62, 63, 64, 65, 66, 67, 68, 134, 135, 136, 137, 138, 139, 140, 215, 219, 225, 229, 236, 237159, 163, 165, 167, 176, 221,43, 161, 164, 166, 168	NC	No Connect These pins MUST be left unconnected.
M14, R13	46, 48	MODE_4M0, MODE_4M1	4M Input Clock Mode 0 to 1 (5 V-Tolerant Input with internal pull-down) These two pins should be tied together and are typically used to select CKi = 4.096 MHz operation. See Table 7, "ZL50023 Operating Modes" on page 32 for a detailed explanation. See Table 13, "Control Register (CR) Bits" on page 39 for CKi and FPi selection using the CKIN1 - 0 bits.
G15, G14, E15, F14	102, 106, 110, 112	FPo0 - 3	ST-BUS/GCI-Bus Frame Pulse Outputs 0 to 3 (5 V-Tolerant Three-state Outputs) FPo0: 8 kHz frame pulse corresponding to the 4.096 MHz output clock of CKo0. FPo1: 8 kHz frame pulse corresponding to the 8.192 MHz output clock of CKo1. FPo2: 8 kHz frame pulse corresponding to 16.384 MHz output clock of CKo2. FPo3: Programmable 8 kHz frame pulse corresponding to 4.096 MHz, 8.192 MHz, 16.384 MHz, or 32.768 MHz output clock of CKo3.
H14, D11, F15	100, 104, 108	FPo_OFF0 - 2	Generated Offset Frame Pulse Outputs 0 to 2 (5 V-Tolerant Three-state Outputs) Individually programmable 8 kHz frame pulses, offset from the output frame boundary by a programmable number of channels.
B7, C7, B5, J6	170, 172, 174, 227	CKo0 - 3	ST-BUS/GCI-Bus Clock Outputs 0 to 3 (5 V-Tolerant Three-state Outputs) CKo0: 4.096 MHz output clock. CKo1: 8.192 MHz output clock. CKo2: 16.384 MHz output clock. CKo3: 4.096 MHz, 8.192 MHz or 16.384 MHz programmable output clock. 32.768 MHz if in multiplied clock mode.

PBGA Pin Number	LQFP Pin Number	Pin Name	Description
B10	155	FPi	ST-BUS/GCI-Bus Frame Pulse Input (5 V-Tolerant Schmitt-Triggered Input) This pin accepts the frame pulse which stays active for 61 ns, 122 ns or 244 ns at the frame boundary. The frame pulse frequency is 8 kHz. The frame pulse associated with the CKi must be applied to this pin. If the data rate is 16.384 Mbps, a 61 ns wide frame pulse must be used. By default, the device accepts a negative frame pulse in ST-BUS format, but it can accept a positive frame pulse instead if the FPINP bit is set high in the Control Register (CR). It can accept a GCI-formatted frame pulse by programming the FPINPOS bit in the Control Register (CR) to high.
B11	154	CKi	ST-BUS/GCI-Bus Clock Input (5 V-Tolerant Schmitt-Triggered Input) This pin accepts a 4.096 MHz, 8.192 MHz or 16.384 MHz clock. In divided clock mode the clock frequency applied to this pin must be twice the highest input or output data rate. In multiplied clock mode the clock frequency applied to this pin must be twice the highest input data rate. The exception is, when data is running at 16.384 Mbps, a 16.384 MHz clock must be used. By default, the clock falling edge defines the input frame boundary, but the device allows the clock rising edge to define the frame boundary by programming the CKINP bit in the Control Register (CR).
B6, C6, D5, D4, B4, B3, C5, C4, E3, C2, B2, D2, F3, F4, E2, F2, E1, D1, G1, F1, J1, H1, K1, L1, A7, A5, A6, A4, A3, A2, C1, B1	179, 180, 181, 182, 183, 184, 185, 187, 198, 200, 201, 202, 203, 204, 205, 206, 243, 244, 245, 246, 247, 248, 250, 252, 189, 190, 191, 192, 193, 194, 196, 197	STi0 - 31	Serial Input Streams 0 to 31 (5 V-Tolerant Inputs with Internal Pull-downs) The data rate of each input stream can be selected independently using the Stream Input Control Registers (SICR[n]). In the 2.048 Mbps mode, these pins accept serial TDM data streams at 2.048 Mbps with 32 channels per frame. In the 4.096 Mbps mode, these pins accept serial TDM data streams at 4.096 Mbps with 64 channels per frame. In the 8.192 Mbps mode, these pins accept serial TDM data streams at 8.192 Mbps with 128 channels per frame. In the 16.384 Mbps mode, these pins accept TDM data streams at 16.384 Mbps with 256 channels per frame.

PBGA Pin Number	LQFP Pin Number	Pin Name	Description
N4, P4, R4, P5, N13, P11, R14, R15, M15, L15, L13, L14, E14, D13, D15, C15, D16, E16, C16, B16, A13, A12, A10, A11, N1, M1, P1, R1, T2, T3, T5, T4	6, 7, 9, 10, 51, 52, 53, 54, 70, 72, 73, 74, 115, 116, 117, 118, 125, 126, 127, 128, 129, 130, 131, 132, 253, 254, 255, 256, 1, 2, 3, 4	STio0 - 31	Serial Output Streams 0 to 31 (5 V-Tolerant Slew-Rate-Limited Three-state I/Os with Enabled Internal Pull-downs) The data rate of each output stream can be selected independently using the Stream Output Control Registers (SOCR[n]). In the 2.048 Mbps mode, these pins output serial TDM data streams at 2.048 Mbps with 32 channels per frame. In the 4.096 Mbps mode, these pins output serial TDM data streams at 4.096 Mbps with 64 channels per frame. In the 8.192 Mbps mode, these pins output serial TDM data streams at 8.192 Mbps with 128 channels per frame. In the 16.384 Mbps mode, these pins output serial TDM data streams at 16.384 Mbps with 256 channels per frame. These output streams can be used as bi-directionals by programming BDH (bit 7) and BDL (bit 6) of Internal Mode Selection (IMS) register.
R3, P6, R5, N5, P12, N15, P13, P15, N16, M16, L16, K16, H16, J16, G16, F16	11, 12, 13, 14, 55, 56, 58, 59, 75, 76, 77, 78, 119, 120, 122, 124	STOHZ0 - 15	Serial Output Streams High Impedance Control 0 to 15 (5 V-Tolerant Slew-Rate-Limited Three-state Outputs) These pins are used to enable (or disable) external three-state buffers. When an output channel is in the high impedance state, the STOHZ drives high for the duration of the corresponding output channel. When the STio channel is active, the STOHZ drives low for the duration of the corresponding output channel. STOHZ outputs are available for STio0 - 15 only.
B15	141	ODE	Output Drive Enable (5 V-Tolerant Input with Internal Pull-up) This is the output enable control for STio0 - 31 and the output-driven-high control for STOHZ0 - 15. When it is high, STio0 - 31 and STOHZ0 - 15 are enabled. When it is low, STio0 - 31 are tristated and STOHZ0 - 15 are driven high.
M4, N6, R6, P7, R7, N7, M8, N8, P8, R8, M9, N9, R9, N10, P9, R10	16, 18, 20, 22, 23, 24, 25, 26, 27, 28, 30, 32, 34, 36, 37, 38	D0 - 15	Data Bus 0 to 15 (5 V-Tolerant Slew-Rate-Limited Three-state I/Os) These pins form the 16-bit data bus of the microprocessor port.

PBGA Pin Number	LQFP Pin Number	Pin Name	Description
N12	44	DTA_RDY	Data Transfer Acknowledgment_Ready (5 V-Tolerant Three-state Output) This active low output indicates that a data bus transfer is complete for the Motorola interface. For the Intel interface, it indicates a transfer is completed when this pin goes from low to high. An external pull-up resistor MUST hold this pin at HIGH level for the Motorola mode. An external pull-down resistor MUST hold this pin at LOW level for the Intel mode.
R11	40	ĊŚ	Chip Select (5 V-Tolerant Input) Active low input used by the Motorola or Intel microprocessor to enable the microprocessor port access.
N11	39	R/W_WR	Read/Write_Write (5 V-Tolerant Input) This input controls the direction of the data bus lines (D0 - 15) during a microprocessor access. For the Motorola interface, this pin is set high and low for the read and write access respectively. For the Intel interface, a write access is indicated when this pin goes low.
R12	42	DS_RD	Data Strobe_Read (5 V-Tolerant Input) This active low input works in conjunction with CS to enable the microprocessor port read and write operations for the Motorola interface. A read access is indicated when it goes low for the Intel interface.
K13, K15, K14, J11, J12, J13, J15, H11, J14, H12, H13, H15, G12, G13	82, 84, 86, 87, 88, 89, 90, 91, 92, 93, 94, 96, 98, 99	A0 - 13	Address 0 to 13 (5 V-Tolerant Inputs) These pins form the 14-bit address bus to the internal memories and registers.
M13	41	MOT_INTEL	Motorola_Intel (5 V-Tolerant Input with Internal Pull-up) This pin selects the Motorola or Intel microprocessor interface to be connected to the device. When this pin is unconnected or connected to high, Motorola interface is assumed. When this pin is connected to ground, Intel interface should be used.
G2	211	RESET	Device Reset (5 V-Tolerant Input with Internal Pull-up) This input (active LOW) puts the device in its reset state that disables the STio0 - 31 drivers and drives the STOHZ0 - 15 outputs to high. It also preloads registers with default values and clears all internal counters. To ensure proper reset action, the reset pin must be low for longer than 1μs. Upon releasing the reset signal to the device, the first microprocessor access cannot take place for at least 600 μs due to the time required to stabilize the device from the power-down state. Refer to Section 13.2 on page 33 for details.

3.0 Device Overview

The device has thirty-two ST-BUS/GCI-Bus inputs (STi0 - 31) and thirty-two ST-BUS/GCI-Bus outputs (STi00 - 31). STi00 - 31 can also be configured as bi-directional pins, in which case STi0 - 31 will be ignored. It is a non-blocking digital switch with 4096 64 kbps channels and is capable of performing rate conversion between ST-BUS/GCI-Bus inputs and ST-BUS/GCI-Bus outputs. The ST-BUS/GCI-Bus inputs accept serial input data streams with data rates of 2.048 Mbps, 4.096 Mbps, 8.192 Mbps and 16.384 Mbps on a per-stream basis. The ST-BUS/GCI-Bus outputs deliver serial data streams with data rates of 2.048 Mbps, 4.096 Mbps and, 8.192 Mbps and 16.384 Mbps on a per-stream basis. The device also provides sixteen high impedance control outputs (STOHZ0 - 15) to support the use of external ST-BUS/GCI-Bus tristate drivers for the first sixteen ST-BUS/GCI-Bus outputs (STi00 -15).

By using Zarlink's message mode capability, microprocessor data stored in the connection memory can be broadcast to the output streams on a per-channel basis. This feature is useful for transferring control and status information for external circuits or other ST-BUS/GCI-Bus devices.

The device uses the ST-BUS/GCI-Bus input frame pulse (FPi) and the ST-BUS/GCI-Bus input clock (CKi) to define the input frame boundary and timing for sampling the ST-BUS/GCI-Bus input streams with various data rates. The output data streams will be driven by and have their timing defined by FPi and CKi in Divided Clock mode (CLKM bit 11 Table 13, Control Register (CR) Bits. In Multiplied Clock mode, the output data streams will be driven by an internally generated clock, which is multiplied from CKi internally. In Multiplied Clock mode, the output data streams will be driven by an internally generated clock, which is multiplied from CKi internally. Refer to Application Note ZLAN-120 for further explanation of the different modes of operation.

There are two clock modes for this device:

The first is the Divided Clock mode. In this mode, output streams are clocked by input CKi. Therefore the output streams have exactly the same jitter as the input streams. The output data rate can be the same as or lower than the input data rate, but the output data rate cannot be higher than what CKi can drive. For example, if CKi is 4.096 MHz, the output data rate cannot be higher than 2.048 Mbps. The second clock mode is called Multiplied Clock mode. In this mode, CKi is used to generate a 16.384 MHz clock internally, and output streams are driven by this internal clock. In Multiplied Clock mode, the data rate of output streams can be any rate, but output jitter may not be exactly the same as input jitter.

A Motorola or Intel compatible non-multiplexed microprocessor port allows users to program the device to operate in various modes under different switching configurations. Users can use the microprocessor port to perform internal register and memory read and write operations. The microprocessor port has a 16-bit data bus, a 14-bit address bus and six control signals (MOT_INTEL, CS, DS_RD, R/W_WR and DTA_RDY).

The device supports the mandatory requirements of the IEEE-1149.1 (JTAG) standard via the test port.

4.0 Data Rates and Timing

The ZL50023 has 32 serial data inputs and 32 serial data outputs. Each stream can be individually programmed to operate at 2.048 Mbps, 4.096 Mbps, 8.192 Mbps or 16.384 Mbps. Depending on the data rate there will be 32 channels, 64 channels, 128 channels or 256 channels, respectively, during a 125 μs frame.

The output streams can be programmed to operate as bi-directional streams. The output streams are divided into two groups to be programmed into bi-directional mode. By setting BDL (bit 6) in the Internal Mode Selection (IMS) register, input streams 0 - 15 (STio - 15) are internally tied low, and output streams 0 - 15 (STio - 15) are set to operate in a bi-directional mode. Similarly, when BDH (bit 7) in the Internal Mode Selection (IMS) register is set, input streams 16 - 31 (STio - 31) are internally tied low, and output streams 16 - 31 (STio - 31) are set to operate in bi-directional mode. The groups do not have to be set into the same mode. Therefore it is possible to have half of the streams operating in bi-directional mode while the other half is operating in normal input/output mode.

The input data rate is set on a per-stream basis by programming STIN[n]DR3 - 0 (bits 3 - 0) in the Stream Input Control Register 0 - 31 (SICR0 - 31). The output data rate is set on a per-stream basis by programming STO[n]DR3 - 0 (bits 3 - 0) in the Stream Output Control Register 0 - 31 (SOCR0 - 31). The output data rates do not have to match or follow the input data rates. The maximum number of channels switched is limited to 4096 channels. If all 32 input streams were operating at 16.384 Mbps (256 channels per stream), this would result in 8192 channels. Memory limitations prevent the device from operating at this capacity. A maximum capacity of 4096 channels will occur if half of the total streams are operating at 16.384 Mbps or all streams are operating at 8.192 Mbps. With all streams operating at 4.09 Mbps, the switching capacity is reduced to 2048 channels. And with all streams operating at 2.048 Mbps, the capacity will be further reduced to 1024 channels. However, as each stream can be programmed to a different data rate, any combination of data rates can be achieved, as long as the total channel count does not exceed 4096 channels. It should be noted that only full stream can be programmed for use. The device does not allow fractional streams.

4.1 External High Impedance Control, STOHZ0 - 15

There are 16 external high impedance control signals, STOHZ0 - 15, that are used to control the external drivers for per-channel high impedance operations. Only the first sixteen ST-BUS/GCI-Bus (STio0 - 15) outputs are provided with corresponding STOHZ signals. The STOHZ outputs deliver the appropriate number of control timeslot channels based on the output stream data rate. Each control timeslot lasts for one channel time. When the ODE pin is high and the OSB (bit 2) of the Control Register (CR) is also high, STOHZ0 - 15 are enabled. When the ODE pin, OSB (bit 2) of the Control Register (CR) or the RESET pin is low, STOHZ0 - 15 are driven high, together with all the ST-BUS/GCI-Bus outputs being tristated. Under normal operation, the corresponding STOHZ outputs of any unused ST-BUS/GCI-Bus channel (high impedance) are driven high. Refer to Figure 16 on page 28 for a diagrammatical explanation.

4.2 Input Clock (CKi) and Input Frame Pulse (FPi) Timing

The frequency of the input clock (CKi) for the ZL50023 depends on the operation mode selected. In divided clock mode, CKi must be at least twice the highest input or output data rate. For example, if the highest input data rate is 4.096 Mbps and the highest output data rate is 8.192 Mbps, the input clock, CKi, must be 16.384 MHz, which is twice the highest overall data rate. The only exception to this is for 16.384 Mbps input or output data. In this case, the input clock, CKi, is equal to the data rate. The input frame pulse, FPi, must always follow CKi. In multiplied clock mode the frequency of CKi must be at least twice the highest input data rate regardless of the output data rate. An APLL is used to multiple CKi to generate an internal clock that is used to output clocks and STio streams. Following the example above, if the highest input data rate is 4.096 Mbps, the input clock, CKi, must be 8.192 MHz, regardless of the output data rate. The only exception to this is for 16.384 Mbps input or output data. In this case, the input clock, CKi, is equal to the data rate. The input frame pulse, FPi, must always follow CKi.

In either mode the user has to program the CKIN1 - 0 (bits 6 - 5) in the Control Register (CR) to indicate the width of the input frame pulse and the frequency of the input clock supplied to the device.

Highest <i>Input or Output</i> Data Rate	CKIN 1-0 Bits	Input Clock Rate (CKi)	Input Frame Pulse (FPi)
8.192 Mbps or 16.384 Mbps	00	16.384 MHz	8 kHz (61 ns wide pulse)
4.096 Mbps	01	8.192 MHz	8 kHz (122 ns wide pulse)
2.048 Mbps	10	4.096 MHz	8 kHz (244 ns wide pulse)

Table 1 - CKi and FPi Configurations for Divided Clock Modes

Highest <i>Input</i> Data Rate	CKIN 1-0 Bits	Input Clock Rate (CKi)	Input Frame Pulse (FPi)
8.192 Mbps or 16.384 Mbps	00	16.384 MHz	8 kHz (61 ns wide pulse)
4.096 Mbps	01	8.192 MHz	8 kHz (122 ns wide pulse)
2.048 Mbps	10	4.096 MHz	8 kHz (244 ns wide pulse)

Table 2 - CKi and FPi Configurations for Multiplied Clock Mode

The ZL50023 accepts positive and negative ST-BUS/GCI-Bus input clock and input frame pulse formats via the programming of CKINP (bit 8) and FPINP (bit 7) in the Control Register (CR). By default, the device accepts the negative input clock format and ST-BUS format frame pulses. However, the switch can also accept a positive-going clock format by programming CKINP (bit 8) in the Control Register (CR). A GCI-Bus format frame pulse can be used by programming FPINPOS (bit 9) and FPINP (bit 7) in the Control Register (CR).

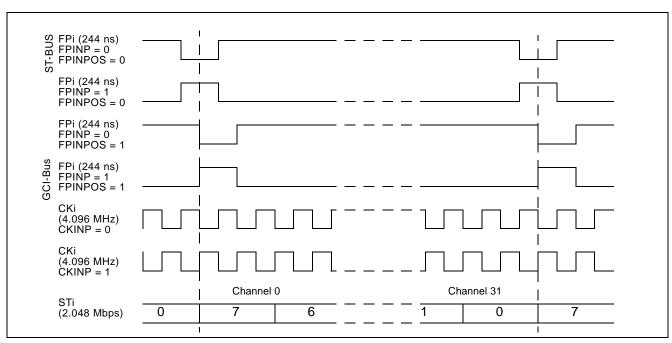


Figure 4 - Input Timing when CKIN1 - 0 bits = "10" in the CR

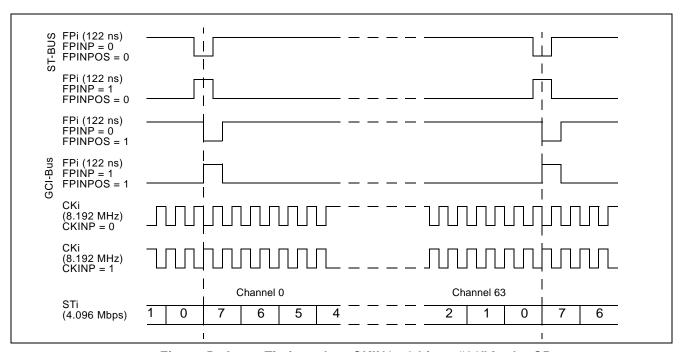


Figure 5 - Input Timing when CKIN1 - 0 bits = "01" in the CR

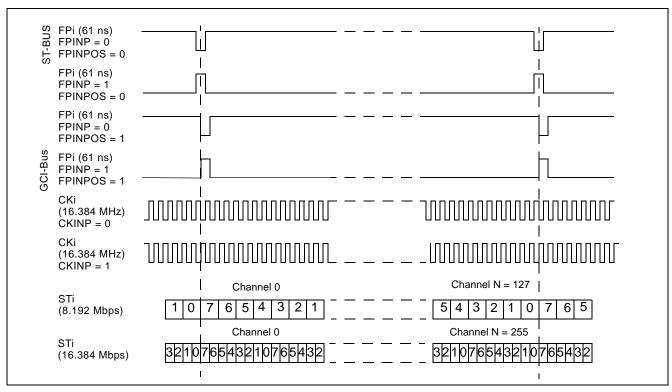


Figure 6 - Input Timing when CKIN1 - 0 = "00" in the CR

5.0 ST-BUS and GCI-Bus Timing

The ZL50023 is capable of operating using either the ST-BUS or GCI-Bus standards. The output timing that the device generates is defined by the bus standard. In the ST-BUS standard, the output frame boundary is defined by the falling edge of CKo while FPo is low. In the GCI-Bus standard, the frame boundary is defined by the rising edge of CKo while FPo goes high. The data rates define the number of channels that are available in a 125 μ s frame pulse period.

By default, the ZL50023 is configured for ST-BUS input and output timing. To set the input timing to conform to the GCI-Bus standard, FPINPOS (bit 9) and FPINP (bit 7) in the Control Register (CR) must be set. To set output timing to conform to the GCI-Bus standard, FPO[n]P and FPO[n]POS must be set in the Output Clock and Frame Pulse Selection Register (OCFSR). The CKO[n]P bits in the Output Clock and Frame Pulse Selection Register control the polarity (positive-going or negative-going) of the output clocks.

6.0 Output Timing Generation

The ZL50023 generates frame pulse and clock timing. There are four output frame pulse pins (FPo0 - 3) and four output clock pins (CKo0 - 3). All output frame pulses are 8 kHz output signals. By default, the output frame boundary is defined by the falling edge of the CKo0, while FPo0 is low. At the output frame boundary, the CKo1, CKo2 and CKo3 output clocks will by default have a falling edge, while FPo1, FPo2 and FPo3 will be low. The duration of the frame pulse low cycle and the frequency of the corresponding output clock are shown in Table 3 on page 21. Every frame pulse and clock output can be tristated by programming the enable bits in the Internal Mode Selection (IMS) register.

Pin Name	Output Timing Rate	Output Timing Unit		
FPo0 pulse width	244	ns		
CKo0	4.096	MHz		
FPo1 pulse width	122	ns		
CKo1	8.192	MHz		
FPo2 pulse width	61	ns		
CKo2	16.384	MHz		
FPo3 pulse width	244, 122, 61 or 30	ns		
CKo3	4.096, 8.192, 16.384 or 32.768	MHz		

Table 3 - Output Timing Generation

The output timing is dependent on the operation mode that is selected. When the device is in Divided Clock mode, the frequencies on CKo0 - 3 cannot be greater than the input clock, CKi. For example, if the input clock is 8.192 MHz, the CKo2 pin will not produce a valid output clock and the CKo3 pin can only be programmed to output a 4.096 MHz or 8.192 MHz clock signal.

The device also delivers positive or negative output frame pulse and ST-BUS/GCI-Bus output clock formats via the programming of various bits in the Output Clock and Frame Pulse Selection Register (OCFSR). By default, the device delivers the negative output clock format. The ZL50023 can also deliver GCI-Bus format output frame pulses by programming bits of the Output Clock and Frame Pulse Selection Register (OCFSR). As there is a separate bit setting for each frame pulse output, some of the outputs can be set to operate in ST-BUS mode and others in GCI-Bus mode.

The following figures describe the usage of the FPO0P, FPO1P, FPO2P, FPO3P, CKO0P, CKO1P, CKO2P and CKO3P bits to generate the FPo0 - 3 and CKo0 - 3 timing.

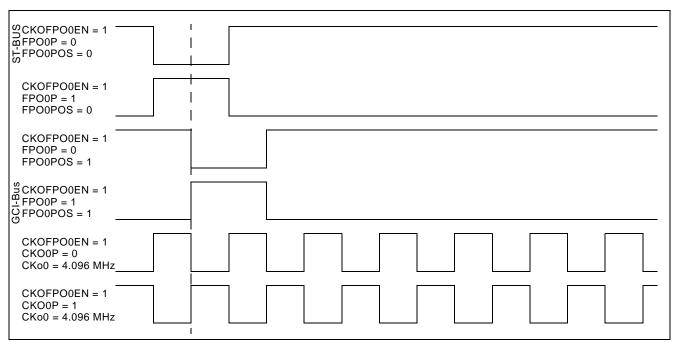


Figure 7 - Output Timing for CKo0 and FPo0

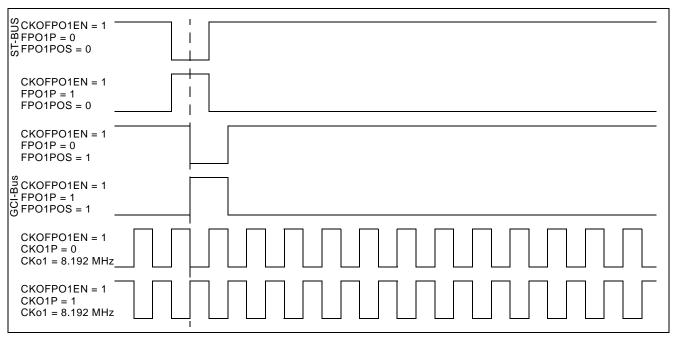


Figure 8 - Output Timing for CKo1 and FPo1

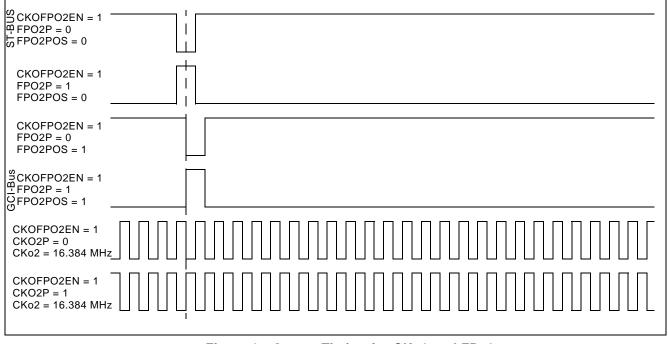


Figure 9 - Output Timing for CKo2 and FPo2

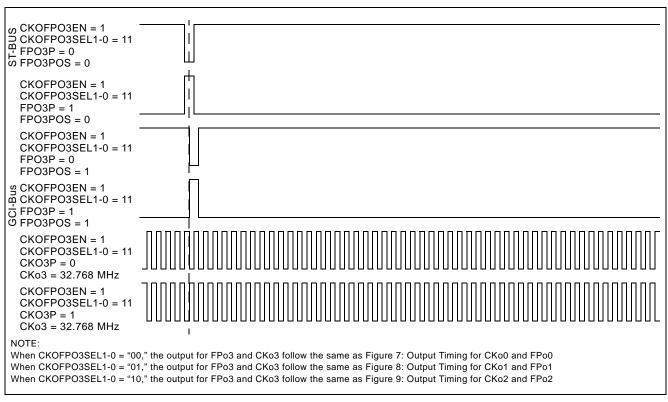


Figure 10 - Output Timing for CKo3 and FPo3 with CKoFPo3SEL1-0="11"

7.0 Data Input Delay and Data Output Advancement

Various registers are provided to adjust the input delay and output advancement for each input and output data stream. The input bit delay and output bit advancement can vary from 0 to 7 bits for each individual stream.

If input delay of less than a bit is desired, different sampling points can be used to handle the adjustments. The sampling point can vary from 1/4 to 4/4 with a 1/4-bit increment for all input streams, unless the stream is operating at 16.384 Mbps, in which case the fractional bit delay has a 1/2-bit increment. By default, the sampling point is set to the 3/4-bit location for non-16.384 Mbps data rates and the 1/2-bit location for the 16.384 Mbps data rate.

The fractional output bit advancement can vary from 0 to 3/4 bits, again with a 1/4-bit increment unless the output stream is operating at 16.384 Mbps, in which case the output bit advancement has a 1/2-bit increment from 0 to 1/2 bit. By default, there is 0 output bit advancement.

Although input delay or output advancement features are available on streams which are operating in bi-directional mode it is not recommended, as it can easily cause bus contention. If users require this function, special attention must be given to the timing to ensure contention is minimized.

7.1 Input Bit Delay Programming

The input bit delay programming feature provides users with the flexibility of handling different wire delays when designing with source streams for different devices.

By default, all input streams have zero bit delay, such that bit 7 is the first bit that appears after the input frame boundary (assuming ST-BUS formatting). The input delay is enabled by STIN[n]BD2-0 (bits 8 - 6) in the Stream Input Control Register 0 - 31 (SICR0 - 31) as described in Table 24 on page 49. The input bit delay can range from 0 to 7 bits.

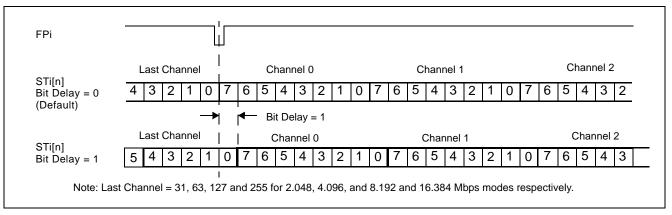


Figure 11 - Input Bit Delay Timing Diagram (ST-BUS)

7.2 Input Bit Sampling Point Programming

In addition to the input bit delay feature, the ZL50023 allows users to change the sampling point of the input bit by programming STIN[n]SMP 1-0 (bits 5 - 4) in the Stream Input Control Register 0 - 31 (SICR0 - 31). For input streams operating at any rate except 16.384 Mbps, the default sampling point is at 3/4 bit and users can change the sampling point to 1/4, 1/2, 3/4 or 4/4 bit position. When the stream is operating at 16.384 Mbps, the default sampling point is 1/2 bit and can be adjusted to a 4/4 bit position.

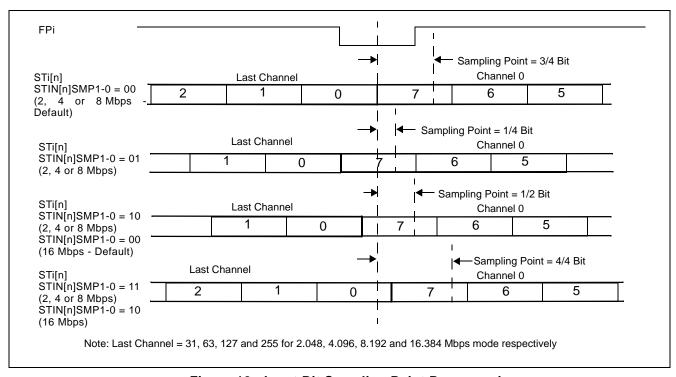


Figure 12 - Input Bit Sampling Point Programming

The input delay is controlled by STIN[n]BD2-0 (bits 8 - 6) to control the bit shift and STIN[n]SMP1 - 0 (bits 5 - 4) to control the sampling point in the Stream Input Control Register 0 - 31 (SICR0 - 31).

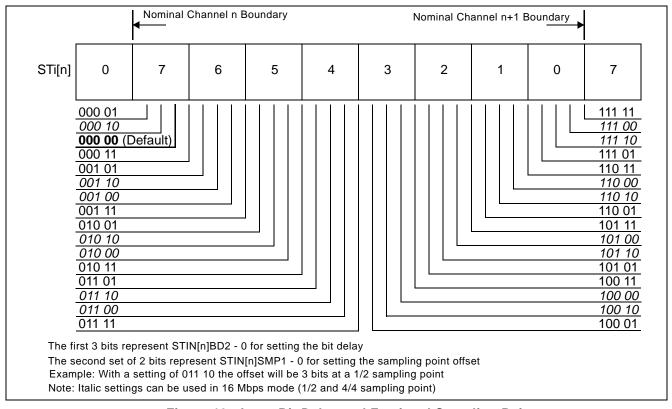


Figure 13 - Input Bit Delay and Factional Sampling Point

7.3 Output Advancement Programming

This feature is used to advance the output data of individual output streams with respect to the output frame boundary. Each output stream has its own bit advancement value which can be programmed in the Stream Output Control Register 0 - 31 (SOCR0 - 31).

By default, all output streams have zero bit advancement such that bit 7 is the first bit that appears after the output frame boundary (assuming ST-BUS formatting). The output advancement is enabled by STO[n]AD 2 - 0 (bits 6 - 4) of the Stream Output Control Register 0 - 31 (SOCR0 - 31) as described in Table 26 on page 53. The output bit advancement can vary from 0 to 7 bits.

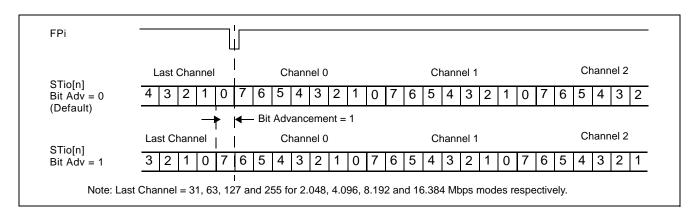


Figure 14 - Output Bit Advancement Timing Diagram (ST-BUS)

7.4 Fractional Output Bit Advancement Programming

In addition to the output bit advancement, the device has a fractional output bit advancement feature that offers better resolution. The fractional output bit advancement is useful in compensating for varying parasitic load on the serial data output pins.

By default all of the streams have zero fractional bit advancement such that bit 7 is the first bit that appears after the output frame boundary. The fractional output bit advancement is enabled by STO[n]FA 1 - 0 (bits 8 - 7) in the Stream Output Control Register 0 - 31 (SOCR0 - 31). For all streams running at any data rate except 16.384 Mbps the fractional bit advancement can vary from 0, 1/4, 1/2 to 3/4 bits. For streams operating at 16.384 Mbps, the fractional bit advancement can be set to either 0 or 1/2 bit.

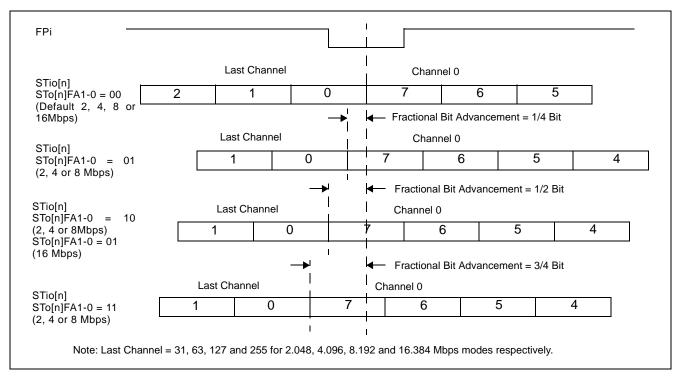


Figure 15 - Output Fractional Bit Advancement Timing Diagram (ST-BUS)

7.5 External High Impedance Control Advancement

The external high impedance signals can be programmed to better match the timing required by the external buffers. By default, the output timing of the STOHZ signals follows the programmed channel delay and bit offset of their corresponding ST-BUS/GCI-Bus output streams. In addition, for all high impedance streams operating at any data rate except 16.384 Mbps, the user can advance the STOHZ signals a further 0, 1/4, 1/2, 3/4 or 4/4 bits by programming STOHZ[n]A 2 - 0 (bit 11 - 9) in the Stream Output Control Register. When the stream is operating at 16.384 Mbps, the additional STOHZ advancement can be set to 0, 1/2 or 4/4 bits by programming the same register.

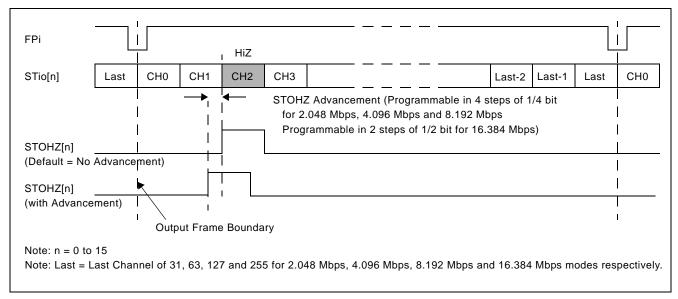


Figure 16 - Channel Switching External High Impedance Control Timing

8.0 Data Delay Through the Switching Paths

The switching of information from the input serial streams to the output serial streams results in a throughput delay. The device can be programmed to perform timeslot interchange functions with different throughput delay capabilities on a per-channel basis. For voice applications, select variable throughput delay to ensure minimum delay between input and output data. In wideband data applications, select constant delay to maintain the frame integrity of the information through the switch. The delay through the device varies according to the type of throughput delay selected by the V/\overline{C} (bit 14) in the Connection Memory Low when CMM = 0.

8.1 Variable Delay Mode

Variable delay mode causes the output channel to be transmitted as soon as possible. This is a useful mode for voice applications where the minimum throughput delay is more important than frame integrity. The delay through the switch can vary from 7 channels to 1 frame + 7 channels. To set the device into variable delay mode, VAREN (bit 4) in the Control Register (CR) must be set before V/C (bit 14) in the Connection Memory Low when CMM = 0. If the VAREN bit is not set and the device is programmed for variable delay mode, the information read on the output stream will not be valid.

In variable delay mode, the delay depends on the combination of the source and destination channels of the input and output streams.

m = input channel number	n-m <= 0	0 < n-m < 7	r	n-m = 7	n-m > 7
n = output channel number			STio < STi	STio >= STi	
T = Delay between input and output	t and output 1 frame - (m-n)		+ (n-m)	n-m	

Table 4 - Delay for Variable Delay Mode

For example, if Stream 4 Channel 2 is switched to Stream 5 Channel 9 with variable delay, the data will be output in the same 125 μ s frame. Contrarily, if Stream 6 Channel 1 is switched to Stream 9 Channel 3, the information will appear in the following frame.

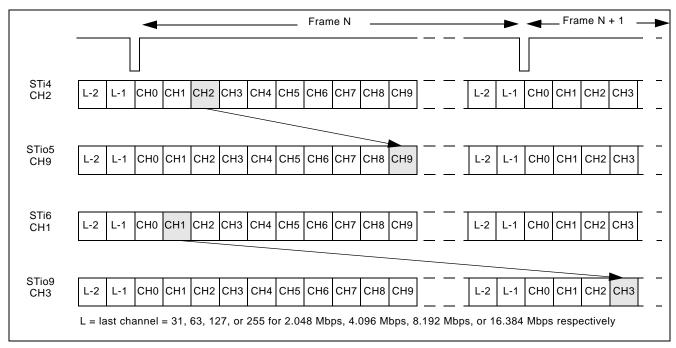


Figure 17 - Data Throughput Delay for Variable Delay

8.2 Constant Delay Mode

In this mode, frame integrity is maintained in all switching configurations. The delay though the switch is 2 frames - Input Channel + Output Channel. This can result in a minimum of 1 frame + 1 channel delay if the last channel on a stream is switched to the first channel of a stream. The maximum delay is 3 frames - 1 channel. This occurs when the first channel of a stream is switched to the last channel of a stream. The constant delay mode is available for all output channels.

The data throughput delay is expressed as a function of ST-BUS/GCI-Bus frames, input channel number (m) and output channel number (n). The data throughput delay (T) is:

$$T = 2 \text{ frames} + (n - m)$$

The constant delay mode is controlled by V/\overline{C} (bit 14) in the Connection Memory Low when CMM = 0. When this bit is set low, the channel is in constant delay mode. If VAREN (bit 4) in the Control Register (CR) is set (to enable variable throughput delay on a chip-wide basis), the device can still be programmed to operate in constant delay mode.

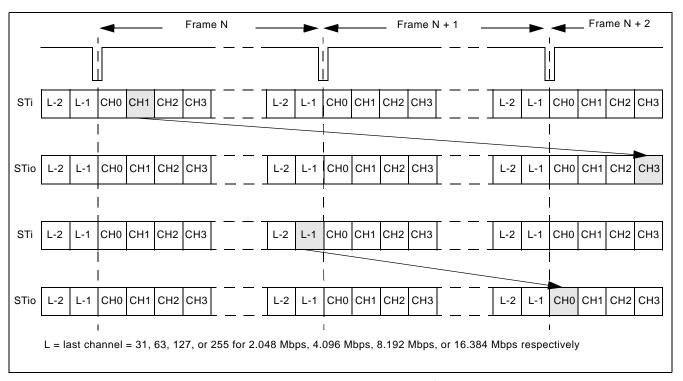


Figure 18 - Data Throughput Delay for Constant Delay

9.0 Connection Memory Description

The connection memory consists of two blocks, Connection Memory Low (CM_L) and Connection Memory High (CM_H). The CM_L is 16 bits wide and is used for channel switching and other special modes. The CM_H is 5 bits wide and is used for the voice coding function. When UAEN (bit 15) of the Connection Memory Low (CM_L) is low, μ -law/A-law conversion will be turned off and the contents of CM_H will be ignored. Each connection memory location of the CM_L or CM_H can be read or written via the 16 bit microprocessor port within one microprocessor access cycle. See Table 31 on page 56 for the address mapping of the connection memory. Any unused bits will be reset to zero on the 16-bit data bus.

For the normal channel switching operation, CMM (bit 0) of the Connection Memory Low (CM_L) is programmed low. SCA7 - 0 (bits 8 - 1) indicate the source (input) channel address and SSA4 - 0 (bits 13 - 9) indicate the source (input) stream address. The 5-bit contents of the CM_H will be ignored during the normal channel switching mode without the μ -law/A-law conversion when UAEN (bit 15) of the Connection Memory Low (CM_L) is set to zero. If μ -law/A-law conversion is required, the CM_H bits must be programmed first to provide the voice/data information, the input coding law and the output coding law before the assertion of UAEN (bit 15) in the Connection Memory Low

When CMM (bit 0) of the Connection Memory Low (CM_L) is programmed high, the ZL50023 will operate in one of the special modes described in Table 33 on page 58. When the per-channel message mode is enabled, MSG7 - 0 (bit 10 - 3) in the Connection Memory Low (CM_L) will be output via the serial data stream as message output data. When the per-channel message mode is enabled, the μ -law/A-law conversion can also be enabled as required.

10.0 Connection Memory Block Programming

This feature allows for fast initialization of the connection memory after power up.

10.1 Memory Block Programming Procedure

- 1. Set MBPE (bit 3) in the Control Register (CR) from low to high.
- 2. Configure BPD2 0 (bits 3 1) in the Internal Mode Selection (IMS) register to the desired values to be loaded into CM L.
- 3. Start the block programming by setting MBPS (bit 0) in the Internal Mode Selection Register (IMS) high. The values stored in BPD2 0 will be loaded into bits 2 0 of all CM_L positions. The remaining CM_L locations (bits 15 3) and the programmable values in the CM_H (bits 4 0) will be loaded with zero values.

The following tables show the resulting values that are in the CM_L and CM_H connection memory locations.

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Value	0	0	0	0	0	0	0	0	0	0	0	0	0	BPD2	BPD1	BPD0

Table 5 - Connection Memory Low After Block Programming

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Table 6 - Connection Memory High After Block Programming

Note: Bits 15 to 5 are reserved in Connection Memory High and should always be 0.

It takes at least two frame periods (250 μs) to complete a block program cycle.

MBPS (bit 0) in the Control Register (CR) will automatically reset to a low position after the block programming process has completed.

MBPE (bit 3) in the Internal Mode Selection (IMS) register must be cleared from high to low to terminate the block programming process. This is not an automatic action taken by the device and must be performed manually.

Note: Once the block program has been initiated, it can be terminated at any time prior to completion by setting MBPS (bit 0) in the Control Register (CR) or MBPE (bit 3) in the Internal Mode Selection (IMS) register to low. If the MBPE bit was used to terminate the block programming, the MBPS bit will have to be set low before enabling other device operations.

11.0 Device Performance Operation in Divided Clock and Multiplied Clock Modes

This device has two main operating modes - Divided Clock mode and Multiplied Clock mode.

In Multiplied Clock mode, output clocks and frame pulses are generated from an internal high-speed clock synchronized to CKi and FPi. Therefore, all specified output clock rates and data rates are available on CKo0-3 and STio0-31. In Divided Clock mode, output clocks and frame pulses are directly divided from CKi/FPi. Therefore, the output clock rate cannot exceed the CKi rate (the output data rates are also limited as per Table 1). The input data rate cannot exceed the CKi rate in either Multiplied or Divided Clock modes, because input data are always sampled directly by CKi.

Table 7, "ZL50023 Operating Modes" on page 32 summarizes the different modes of operation available within the ZL50023. Each Major mode (explained below) has various associated Minor modes that are determined by setting

the MODE_4M Input Control pins and the OPM bit in the Control Register (Table 13, "Control Register (CR) Bits" on page 39) indicated in the table.

Devic	Device		Input Pins		Output Clock I	Data Pins		
Operating	Mode	Control	Signal	Bit	Reference Lock	Enabled	(Clock Source
Major	Minor	MODE_4M [1:0]	CKi	OPM	CKo0-3	CKo0-3	STi	STo
Divided	4 M	11	4 M	0	CKi	Yes	CKi	CKo0-3
Clock	8/16 M	00	8/16 M					(CKi)
Multiplied	4 M	11	4 M	1	CKi MULT			CKo0-3
Clock	8/16 M	00	8/16 M					(CKi MULT)

Leaend:

Reference Lock - Refers to what signal the output pins are locked to:

Cki = Bypass. Cki is passed directly through to CKo0-3.

Cki MULT = Cki is passed through clock multiplier to CKo0-3.

Clock Source - Refers to which clock samples STi and which clock outputs STo; STi applies when STi or STio is input; STo applies when STio is output.

Table 7 - ZL50023 Operating Modes

11.1 Divided Clock Mode Operation

When the device is in Divided Clock mode, STio0 - 31 are driven by CKi. In this mode, the output streams and clocks have the same amount of jitter as the input clock (CKi), but the input and output data rate cannot exceed the input data rate defined by CKi. For example, if CKi is 4.096 MHz, the input and output data rate cannot be higher than 2.048 Mbps, and the generated output clock rates cannot exceed 4.096 MHz.

11.2 Multiplied Clock Mode Operation

When the device is in Multiplied Clock mode, device hardware is used to multiply CKi internally. STio0 - are driven by this internally generated clock. In this mode, the output clocks and data can run at any of the specified rates, but they may have different jitter characteristics from the input clock (CKi). The input data rates are still limited by the CKi rate (as per Table 1), as input data are always sampled directly by CKi.

11.3 Output Clock Frequencies

The device can generate a limited number of clock and frame pulse output signals. All signals are synchronous to each other and are locked to the input CKi and FPi. The device can provide outputs with the following frequencies, with the exception that when in Divided Clock mode, the output clock rate cannot exceed the input CKi rate.

CKo0	4.096 MHz
CKo1	8.192 MHz
CKo2	16.384 MHz
CKo3	4.096 MHz, 8.192 MHz, 16.384 MHz or 32.768 MHz
FPo0	8 kHz (244 ns wide pulse)
FPo1	8 kHz (122 ns wide pulse)
FPo2	8 kHz (61 ns wide pulse)
FPo3	8 kHz (244 ns, 122 ns, 61 ns or 30 ns wide pulse)

Table 8 - Generated Output Frequencies

X - Don't care or not applicable.

12.0 Microprocessor Port

The device provides access to the internal registers, connection memories and data memories via the microprocessor port. The microprocessor port is capable of supporting both Motorola and Intel non-multiplexed microprocessors. The microprocessor port consists of a 16-bit parallel data bus (D15 - 0), 14-bit address bus (A13 - 0) and six control signals (MOT_INTEL, CS, DS_RD, R/W_WR and DTA_RDY).

The data memory can only be read from the microprocessor port. For a data memory read operation, D7 - 0 will be used and D15 - 8 will output zeros.

For a CM_L read or write operation, all bits (D15 - 0) of the data bus will be used. For a CM_H write operation, D4 - 0 of the data bus must be configured and D15 - 5 are ignored. D15 - 5 must be driven either high or low. For a CM_H read operation, D4 - 0 will be used and D15 - 5 will output zeros.

Refer to Figure 20 on page 62, Figure 21 on page 63, Figure 22 on page 64 and Figure 23 on page 65 for the microprocessor timing.

13.0 Device Reset and Initialization

The RESET pin is used to reset the ZL50023. When this pin is low, the following functions are performed:

- · synchronously puts the microprocessor port in a reset state
- tristates the STio0 31 outputs
- · drives the STOHZ0 15 outputs to high
- preloads all internal registers with their default values (refer to the individual registers for default values)
- · clears all internal counters

13.1 Power-up Sequence

The recommended power-up sequence is for the V_{DD_IO} supply (normally +3.3 V) to be established before the power-up of the V_{DD_CORE} supply (normally +1.8 V). The V_{DD_CORE} supply may be powered up at the same time as V_{DD_IO} , but should not "lead" the V_{DD_IO} supply by more than 0.3 V.

13.2 Device Initialization on Reset

Upon power up, the ZL50023 should be initialized as follows:

- Set the ODE pin to low to disable the STio0 31 outputs and to drive STOHZ0 15 to high
- Set the TRST pin to low to disable the JTAG TAP controller
- Reset the device by pulsing the RESET pin to zero for longer than 1 μs
- After releasing the RESET pin from low to high, wait for a certain period of time (see Note below) for the
 device to stabilize from the power down state before the first microprocessor port access can occur
- Program CKIN1 0 (bit 6 -5) in the Control Register (CR) to define the frequency of the CKi and FPi inputs
- Wait at least 500 μs prior to the next microport access (see Note below)
- Use the block programming mode to initialize the connection memory
- Release the ODE pin from low to high after the connection memory is programmed

Note: If CKi is 16.384 MHz, the waiting time is 500 μ s; if CKi is 8.192 MHz, the waiting time is 1 ms; if CKi is 4.096 MHz, the waiting time is 2 ms.

13.3 Software Reset

In addition to the hardware reset from the \overline{RESET} pin, the device can also be reset by using software reset SRSTSW (bit 1) in the Software Reset Register (SRR).

14.0 Pseudorandom Bit Generation and Error Detection

The ZL50023 has one Bit Error Rate (BER) transmitter and one BER receiver for each pair of input and output streams, resulting in 32 transmitters connected to the output streams and 32 receivers associated with the input streams. Each transmitter can generate a BER sequence with a pattern of 2^{15} -1 pseudorandom code (ITU O.151). Each transmitter can start at any location on the stream and will last for a minimum of 1 channel to a maximum of 1 frame time (125 μ s). The BER receivers and transmitters are enabled by programming the RBEREN (bit 5) and TBEREN (bit 4) in the IMS register. In order to save power, the 32 transmitters and/or receivers can be disabled. (This is the default state.)

Multiple connection memory locations can be programmed for BER tests such that the BER patterns can be transmitted for multiple consecutive output channels. If consecutive input channels are not selected, the BER receiver will not compare the bit patterns correctly. The number of output channels which the BER pattern occupies has to be the same as the number of channels defined in the BER Length Register (BRLR) which defines how many BER channels are to be monitored by the BER receiver.

For each input stream, there is a set of registers for the BER test. The registers are as follows:

- BER Receiver Control Register (BRCR) ST[n]CBER (bit 1) is used to clear the Bit Receiver Error Register (BRER). ST[n]SBER (bit 0) is used to enable the per-stream BER receiver.
- BER Receiver Start Register (**BRSR**) ST[n]BRS7 0 (bit 7 0) defines the input channel from which the BER sequence will start to be compared.
- BER Receiver Length Register (BRLR) ST[n]BL8 0 (bit 8 0) define how many channels the sequence will last. Depending on the data rate being used, the BER test can last for a maximum of 32, 64, 128 or 256 channels at the data rates of 2.048, 4.096, 8.192 or 16.384 Mbps, respectively. The minimum length of the BER test is a single channel. The user must take care to program the correct channel length for the BER test so that the channel length does not exceed the total number of channels available in the stream.
- BER Receiver Error Register (BRER) This read-only register contains the number of counted errors. When
 the error count reaches 0xFFFF, the BER counter will stop updating so that it will not overflow. ST[n]CBER
 (bit 1) in the BER Receiver Control Register is used to reset the BRER register.

For normal BER operation, CMM (bit 0) must be 1 in the Connection Memory Low (CM_L). PCC1 - 0 (bits 2 - 1) in the Connection Memory Low must be programmed to "10" to enable the per-stream based BER transmitters. For each stream, the length (or total number of channels) of BER testing can be as long as one whole frame, but the channels MUST be consecutive. Upon completion of programming the connection memory, the corresponding BER receiver can be started by setting ST[n]SBER (bit 0) in the BRCR to high. There must be at least 2 frames (250 µs) between completion of connection memory programming and starting the BER receiver before the BER receiver can correctly identify BER errors. A 16-bit BER counter is used to count the number of bit errors.

15.0 PCM A-law/μ-law Translation

The ZL50023 provides per-channel code translation to be used to adapt pulse code modulation (PCM) voice or data traffic between networks which use different encoding laws. Code translation is valid in both Connection Mode and Message Mode.

In order to use this feature, the Connection Memory High (CM_H) entry for the output channel must be programmed. \overline{V}/D (bit 4) defines if the traffic in the channel is voice or data. Setting ICL1 - 0 (bits 3 - 2) programs the input coding law and OCL1 - 0 (bits 1- 0) programs the output coding law as shown in Table 9.

The different code options are:

Input Coding (ICL1- 0)	Output Coding (OCL1 - 0)	Voice Coding (V/D bit = 0)	Data Coding (V/D bit = 1)
00	00	ITU-T G.711 A-law	No code
01	01	ITU-T G.711 μ-law	Alternate Bit Inversion (ABI)
10	10	A-law without Alternate Bit Inversion (ABI)	Inverted Alternate Bit Inversion (ABI)
11	11	μ-law without Magnitude Inversion (MI)	All bits inverted

Table 9 - Input and Output Voice and Data Coding

For voice coding options, the ITU-T G.711 A-law and ITU-T G.711 μ -law are the standard rules for encoding. A-law without Alternate Bit Inversion (ABI) is an alternative code that does not invert the even bits (6, 4, 2, 0). μ -law without Magnitude Inversion (MI) is an alternative code that does not perform inversion of magnitude bits (6, 5, 4, 3, 2, 1, 0).

When transferring data code, the option "no code" does not invert the bits. The Alternate Bit Inversion (ABI) option inverts the even bits (6, 4, 2, 0) while the Inverted Alternate Bit Inversion (ABI) inverts the odd bits (7, 5, 3, 1). When the "All bits inverted" option is selected, all of the bits (7, 6, 5, 4, 3, 2, 1, 0) are inverted.

The input channel and output channel encoding law are configured independently. If the output channel coding is set to be different from the input channel, the ZL50023 performs translation between the two standards. If the input and output encoding laws are set to the same standard, no translation occurs. As the \overline{V}/D (bit 4) of the Connection Memory High (CM_H) must be set on a per-channel basis, it is not possible to translate between voice and data encoding laws.

16.0 Quadrant Frame Programming

By programming the Stream Input Quadrant Frame Registers (SIQFR0 - 31), users can divide one frame of input data into four quadrant frames and can force the LSB or MSB of every input channel in these quadrants to one or zero for robbed-bit signaling. The four quadrant frames are defined as follows:

Data Rate	Quadrant 0	Quadrant 1	Quadrant 2	Quadrant 3
2.048 Mbps	Channel 0 - 7	Channel 8 - 15	Channel 16 - 23	Channel 24 - 31
4.096 Mbps	Channel 0 - 15	Channel 16 - 31	Channel 32 - 47	Channel 48 - 63
8.192 Mbps	Channel 0 - 31	Channel 32 - 63	Channel 64 - 95	Channel 96 - 127
16.384 Mbps	Channel 0 - 63	Channel 64 - 127	Channel 128 - 191	Channel 192 - 255

Table 10 - Definition of the Four Quadrant Frames

When the quadrant frame control bits, STIN[n]Q3C2 - 0 (bit 11 - 9), STIN[n]Q2C2 - 0 (bit 8 - 6), STIN[n]Q1C2 - 0 (bit 5 - 3) or STIN[n]Q1C2 - 0 (bit 2 - 0), are set, the LSB or MSB of every input channel in the quadrant is forced to "1" or "0" as shown by the following table:

STIN[n]Q[y]C[2:0]	Action
0xx	Normal Operation
100	Replaces LSB of every channel in Quadrant y with '0'
101	Replaces LSB of every channel in Quadrant y with '1'
110	Replaces MSB of every channel in Quadrant y with '0'
111	Replaces MSB of every channel in Quadrant y with '1'
Note: y = 0, 1, 2, 3	

Table 11 - Quadrant Frame Bit Replacement

Note that Quadrant Frame Programming and BER reception cannot be used simultaneously on the same input stream.

17.0 JTAG Port

The JTAG test port is implemented to meet the mandatory requirements of the IEEE-1149.1 (JTAG) standard. The operation of the boundary-scan circuitry is controlled by an external Test Access Port (TAP) Controller.

17.1 Test Access Port (TAP)

The Test Access Port (TAP) accesses the ZL50023 test functions. It consists of three input pins and one output pin as follows:

- Test Clock Input (TCK) TCK provides the clock for the test logic. TCK does not interfere with any on-chip
 clock and thus remains independent in the functional mode. TCK permits shifting of test data into or out of
 the Boundary-Scan register cells concurrently with the operation of the device and without interfering with
 the on-chip logic.
- Test Mode Selection Inputs (TMS) The TAP Controller uses the logic signals received at the TMS input to control test operations. The TMS signals are sampled at the rising edge of the TCK pulse. This pin is internally pulled to high when it is not driven from an external source.
- **Test Data Input (TDi)** Serial input data applied to this port is fed either into the instruction register or into a test data register, depending on the sequence previously applied to the TMS input. The registers are described in a subsequent section. The received input data is sampled at the rising edge of the TCK pulse. This pin is internally pulled to high when it is not driven from an external source.
- Test Data Output (TDo) Depending on the sequence previously applied to the TMS input, the contents of either the instruction register or test data register are serially shifted out towards TDo. The data from TDo is clocked on the falling edge of the TCK pulses. When no data is shifted through the boundary scan cells, the TDo driver is set to a high impedance state.
- Test Reset (TRST) Resets the JTAG scan structure. This pin is internally pulled to high when it is not
 driven from an external source.

17.2 Instruction Register

The ZL50023 uses the public instructions defined in the IEEE-1149.1 standard. The JTAG interface contains a four-bit instruction register. Instructions are serially loaded into the instruction register from the TDi when the TAP Controller is in its shifted-OR state. These instructions are subsequently decoded to achieve two basic functions: to select the test data register that may operate while the instruction is current and to define the serial test data register path that is used to shift data between TDi and TDo during data register scanning.

17.3 Test Data Registers

As specified in the IEEE-1149.1 standard, the ZL50023 JTAG interface contains three test data registers:

- The Boundary-Scan Register The Boundary-Scan register consists of a series of boundary-scan cells arranged to form a scan path around the boundary of the ZL50023 core logic.
- The Bypass Register The Bypass register is a single stage shift register that provides a one-bit path from TDi to TDo.
- The Device Identification Register The JTAG device ID for the ZL50023 is 0C36714BH

Version	<31:28>	0000
Part Number	<27:12>	1100 0011 0110 0111
Manufacturer ID	<11:1>	0001 0100 101
LSB	<0>	1

17.4 BSDL

A Boundary Scan Description Language (BSDL) file is available from Zarlink Semiconductor to aid in the use of the IEEE-1149.1 test interface.

18.0 Register Address Mapping

Address A13 - A0	CPU Access	Register Name	Abbreviation	Reset By
0000 _H	R/W	Control Register	CR	Switch/Hardware
0001 _H	R/W	Internal Mode Selection Register	IMS	Switch/Hardware
0002 _H	R/W	Software Reset Register	SRR	Hardware Only
0003 _H	R/W	Output Clock and Frame Pulse Control Register	OCFCR	Hardware
0004 _H	R/W	Output Clock and Frame Pulse Selection Register	OCFSR	Hardware
0005 _H	R/W	FPo_OFF0 Register	FPOFF0	Hardware
0006 _H	R/W	FPo_OFF1 Register	FPOFF1	Hardware
0007 _H	R/W	FPo_OFF2 Register	FPOFF2	Hardware
0010 _H	R Only	Internal Flag Register	IFR	Switch/Hardware
0011 _H	R Only	BER Error Flag Register 0	BERFR0	Switch/Hardware
0012 _H	R Only	BER Error Flag Register 1	BERFR1	Switch/Hardware
0013 _H	R Only	BER Receiver Lock Register 0	BERLR0	Switch/Hardware
0014 _H	R Only	BER Receiver Lock Register 1	BERLR1	Switch/Hardware
0100 _H - 011F _H	R/W	Stream Input Control Registers 0 - 31	SICR0 - 31	Switch/Hardware
0120 _H - 013F _H	R/W	Stream Input Quadrant Frame Registers 0 - 31	SIQFR0 - 31	Switch/Hardware
0200 _H - 021F _H	R/W	Stream Output Control Registers 0 - 31	SOCR0 - 31	Switch/Hardware
0300 _H - 031F _H	R/W	BER Receiver Start Registers 0 - 31	BRSR0 - 31	Switch/Hardware
0320 _H - 033F _H	R/W	BER Receiver Length Registers 0 - 31	BRLR0 - 31	Switch/Hardware
0340 _H - 035F _H	R/W	BER Receiver Control Registers 0 - 31	BRCR0 - 31	Switch/Hardware
0360 _H - 037F _H	R Only	BER Receiver Error Registers 0 - 31	BRER0 - 31	Switch/Hardware

Table 12 - Address Map for Registers (A13 = 0)

19.0 Detailed Register Description

	rnal Read et Value:	d/Write Addr 0000 _H	ess: 000	0 _H											
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	OPM	0	FPIN POS	CKINP	FPINP	CKIN 1	CKIN 0	VAR EN	MBPE	OSB	MS1	MS0

		1				
Bit	Name			Description		
15 - 12	Unused	Reserved.	In normal functiona	al mode, these bits MUS	T be set to zero.	
11	OPM	Operation This bit is to Operating N		ice in Master/Slave ope for more details.	ration. Refer to Table	e 7, "ZL50023
10	Unused	Reserved.	In normal functiona	al mode, these bits MUS	T be set to zero.	
9	FPINPOS	When this b	ne Pulse (FPi) Pos bit is low, FPi strado bit is high, FPi starts	ition dles frame boundary (as s from frame boundary (a	defined by ST-BUS) as defined by GCI-B	ne)
8	CKINP	When this b		lling edge aligns with the ising edge aligns with th		
7	FPINP	When this		rity It frame pulse FPi has frame pulse FPi has the		
6 - 5	CKIN1 - 0	Input Cloc	k (CKi) and Frame	Pulse (FPi) Selection		
			CKIN1 - 0	FPi Active Period	CKi	
			00	61 ns	16.384 MHz	1
			01	122 ns	8.192 MHz	1
			10	244 ns	4.096 MHz	1
			11	Reser	ved	1
				4M1 pins, as described i e input clock mode.	n "Pin Description" o	n page 10,
4	VAREN	When this b	elay Mode Enable bit is low, the variab bit is high, the varia	le delay mode is disable ble delay mode is enable	ed on a device-wide bed on a device-wide	pasis. basis.
3	MBPE	When this	lock Programming bit is high, the conection memo	j Enable inection memory block iry. When it is low, the mo	programming mode emory block program	is enabled to ming mode is

Table 13 - Control Register (CR) Bits

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
0	0	0	0	OPM	0	FPIN POS	CKINP	FPINP	CKIN 1	CKIN 0	VAR EN	MBPE	OSB	MS1	MS0	
Bit	N	ame						De	scripti	on						
2	C	OSB	This b		es the	STio() - 31 ar of the s				erial ou	itputs. 7	he foll	lowing	table	
			Ī	RESET Pin		TSW SRR)	ODE Pin	OSB Bit	S	Tio0 - 3	1		STOH	Z0 - 15		
				0)	X	Х	Х		HiZ			Driver	n High		
				1		1	Χ	Х		HiZ			Driver	n High		
				1	()	0	Х		HiZ			Driver	n High		
				1)	1	0		HiZ			Driver			
				1	(0	1	1	(Cont	Active rolled by	y CM)	(C	Act ontrolle	ive ed by Cl	M)	
				Unused R0 - 31 (ams are	tristate	d (STio	= HiZ,	STOF	IZ = Dri	ven Hi	igh). R	efer	
1 - 0	MS	S1 - 0	These	ory Sele two bit r access	s are	used to	o select	connec	tion me	emory I	ow, co	nnectio	n high	or data	a me	
				ı	MS1 -	0			Memo	ry Sele	ction					
					00			Connec	tion Me	mory Lo	w Rea	d/Write		1		
					01			Connect	ion Mer	mory Hi	gh Rea	d/Write		1		
					10				Data M	lemory	Read			1		
			1											-1		

Table 13 - Control Register (CR) Bits (continued)

External F Reset Val			dress	: 0001 _H											
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	STIO_ PD_EN	BDH	BDL	RBER EN	TBER EN	BPD 2	BPD 1	BPD 0	MBPS
Bit	N	lame							Descr	iption					
15 - 9	Ur	nused		Rese	rved. In	norma	al functio	nal mo	de, thes	e bits N	//UST b	e set t	o zero		
8		O_PD EN	_	Wher		is low	nable , the pull n, the pu								
7	E	BDH		Bi-di	ectiona	al Con	trol for \$	Stream	s 16-31						
							BDH	S	Tio16 - 3	31 Opera	ation				
							0		STi16-3	operation 1 are inp 1 are out	outs				
							1	STi	16-31 tie	nal opera d low in re bi-dire	ternally				
6	ı	BDL		Bi-di	ectiona	al Con	trol for \$	Stream	s 0-15						
							BDL	S	Tio0 - 1	5 Opera	ition				
							0		STi0-15	operation are input are out	uts				
							1	ST	0-15 tied	nal opera d low into e bi-dire	ernally				
5	RB	BEREN	1	Wher	Receing this bit it MUST	is low	, all the E	BER red	eivers a	are disa	abled. T	o enat	ole any	/ BER	receivers,
4	ТВ	EREN	I	Wher	this b	it is lo	Enable ow, all the MUST be			nitters	are dis	abled.	To e	nable	any BER
3 - 1	BP	PD2 - ()	These memory Register the bit	e bits re ory bloc ter is se ts BPD2 e Conne	fer to to to the fer to hid hid to hid hid hid to hid	gramming igh and t re loaded	g featur he MBF d into bi	e is ac PS bit ir ts 2 - 0	tivated. this re of the 0	After t gister is Connec	the ME s set to tion M	BPE book book by the base but be builded by the builded builded by the builded by the builded builded by the builded builded by the builded bui	it in th , the c Low.	enever the ne Control ontents of Bits 15 - 3 High are

Table 14 - Internal Mode Selection Register (IMS) Bits

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	STIO_ PD_EN	BDH	BDL	RBER EN	TBER EN	BPD 2	BPD 1	BPD 0	MBPS

Bit	Name	Description
0	MBPS	Memory Block Programming Start: A zero to one transition of this bit starts the memory block programming function. The MBPS and BPD2 - 0 bits in this register must be defined in the same write operation. Once the MBPE bit in the Control Register is set to high, the device requires two frames to complete the block programming. After the programming function has finished, the MBPS bit returns to low, indicating the operation is completed. When MBPS is high, MBPS or MBPE can be set to low to abort the programming operation. Whenever the microprocessor writes a one to the MBPS bit, the block programming function is started. As long as this bit is high, the user must maintain the same logical value to the other bits in this register to avoid any change in the device setting.

Table 14 - Internal Mode Selection Register (IMS) Bits (continued)

	ead/Write e: 0000 _H		33. 0002	Н											
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	0	0	0	0	0	0	0	SRST SW	0

Bit	Name	Description
15 - 2	Unused	Reserved In normal functional mode, these bits MUST be set to zero.
1	SRSTSW	Software Reset Bit for Switch When this bit is low, switching blocks are in normal operation. When this bit is high, switching blocks are in software reset state. Refer to Table 12, "Address Map for Registers (A13 = 0)" on page 32 for details regarding which registers are affected.
0	Unused	Reserved In normal functional mode, these bits MUST be set to zero.

Table 15 - Software Reset Register (SRR) Bits

Externa Reset \			Addres	s: 0003 _H											
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	FPOF2 EN	FPOF1 EN	FPOF0 EN	0	0	CKO FPO3 EN	CKO FPO2 EN	CKO FPO1 EN	CKO FPO0 EN
Bit		Nam	е						Descr	iption					
15 - 9		Unuse	ed	Rese		nction	al mode	, these b	its MUS T	r be se	t to zer	0.			
8	F	POF2	EN	When	OFF2 this b this b	it is hi	l e gh, outpo w, outpu	ut frame t frame p	pulse FF oulse FPo	Po_OFF o_OFF2	-2 2.				
7	F	FPOF1	EN	When		it is hi	le gh, outpo w, outpu						edance	e state.	
6	F	POF0	EN	FPo_ When			le gh, outp	ut frame	pulse FF	Po_OFF	0 is en	abled.			

In normal functional mode, these bits MUST be set to zero.

In normal functional mode, these bits MUST be set to zero.

When this bit is low, CKo3 and FPo3 are in high impedance state.

Unused

Unused

CKOFPO3

ΕN

CKOFPO2

ΕN

CKOFPO1

ΕN

CKOFPO0

ΕN

Reserved

Reserved

CKo3 and FPo3 Enable

CKo2 and FPo2 Enable

CKo1 and FPo1 Enable

CKo₀ and FPo₀ Enable

5

4

3

2

1

0

When this bit is low, output frame pulse FPo_OFF0 is in high impedance state.

When this bit is high, output clock CKo3 and output frame pulse FPo3 are enabled.

When this bit is high, output clock CKo2 and output frame pulse FPo2 are enabled. When this bit is low, CKo2 and FPo2 are in high impedance state.

When this bit is high, output clock CKo1 and output frame pulse FPo1 are enabled. When this bit is low, CKo1 and FPo1 are in high impedance state.

When this bit is high, output clock CKo0 and output frame pulse FPo0 are enabled.

Table 16 - Output Clock and Frame Pulse Control Register (OCFCR) Bits

When this bit is low, CKo0 and FPo0 are in high impedance state.

15	lue: 0	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	CKO FPO3 SEL1	CKO FPO3 SEL0	CKO3 P	FPO3 P	FPO3 POS	CKO2 P	FPO2 P	FPO2 POS	CKO1 P	FPO1 P	FPO1 POS	CKO0 P	FPO0 P	FPO(POS
Dir		NI				1	•		D i-	-41	1		•		
Bit 15 - 14		Name Unused		Reserve					Descri	otion					
15 - 14		Unusea		n norma		onal mo	ode, the	se bits	MUST	be set	to zero				
13 - 12		KOFPC SEL1 - (Output (Selection		(CKo3)	Frequ	ency a	and Ou	itput F	rame I	Pulse ((FPo3)	Pulse	Cycl
						CKOF SEL	PO3 1 - 0		FPo3		С	Ko3			
						0	0		244 ns		4.09	6 MHz			
						0			122 ns			2 MHz			
						11			61 ns			34 MHz			
						1 ⁻	I		30 ns		32.76	68 MHz			
11		CKO3P	V	Output C Vhen the	is bit	is low,	the o	itput c	lock C						
				ame bo		•	51C 10 111	gn, tne	outpu	CIOCK	01100	J		3	ith th
10		FPO3P	fı C V	-	undary rame s bit is	Pulse (FPo3)	Polarity frame	y Select	ction Po3 ha	as the n	egative	e frame	pulse f	orma
10		FPO3P PO3PO	fi V V S	rame bo Output F Vhen thi	rame s bit is s bit is rame s bit is	Pulse (low, the high, th Pulse (low, FF	FPo3) e outpute output	Polarity frame at frame Position ddles f	y Select pulse F e pulse on rame b	ction Po3 ha FPo3 h	as the neas the	egative	e frame e frame oy ST-E	pulse f pulse f BUS).	orma
	F		S C V V V b	Tame bo Output F When thi When thi Output F When thi	rame s bit is clock (is bit v. When	Pulse (low, the high, th Pulse (low, FF high, F CKo2) is low, n this b	FPo3) Po3 stra Po3 sta Po4 sta Po4 sta Po4 sta	Polarity frame at frame Positio ddles f arts from	y Selection y Selection rame botton lock C	etion Po3 has FPo3 has been boundare boundare	as the nas the y (as dary (as	egative positive efined I define	e frame e frame by ST-E d by Go	pulse f pulse f BUS). CI-Bus)	orma
9	F	PO3PO	S C V V V D D D D D D D D D D D D D D D D	Output F When thi When thi Output F When thi When thi Output C When th oundary	rame s bit is clock (is bit when any of the content of the c	Pulse (low, the high, the Pulse (low, FF high, FCKo2) is low, nothing the Pulse (low, the low, the low	FPo3) Po3 stra Po3 stra Polarit the or bit is hi	Polarity frame ddles farts from y Selection gh, the	y Selection rame be frame ction lock C outpu y Selection	etion FPo3 has FPo3 has boundare boundare boundare tolock	as the nas the y (as dary (as dary (as CKo2	efined I defined defined dge ali	e frame e frame by ST-E d by Go igns wiedge al	pulse f pulse f BUS). CI-Bus) th the ligns w	orma

Table 17 - Output Clock and Frame Pulse Selection Register (OCFSR) Bits

15	14	13	12	2 11	10	9	8	7	6	5	4	3	2	1	0
0	0	CKO FPO3 SEL1	CK(FPC SEL	D3 P	FPO3 P	FPO3 POS	CKO2 P	FPO2 P	FPO2 POS	CKO1 P	FPO1 P	FPO1 POS	CKO0 P	FPO0 P	FPO0 POS
	1														
Bit															
5		CKO1P		Output (When the boundary frame bo	nis bit ` y. Whe	is low, n this l	the o	utput c	lock C						
4		FPO1P		Output I When th When th	is bit is	low, the	e outpu	t frame	pulse F	Po1 ha		_			
3	F	PO1PO	S	Output I When th When th	is bit is	low, FF	o1 stra	iddles f	rame b).
2		CKO0P		Output (When the boundary frame bo	nis bit y. Whe	is low, n this l	the o	utput c	lock C						
1		FPO0P		Output I When th When th	is bit is	low, the	outpu	t frame	pulse F	Po0 ha		_			
0	FI	PO0PO	S	Output I When th						oundar	v (as d	efined	hv ST-F	RIIS)	

Table 17 - Output Clock and Frame Pulse Selection Register (OCFSR) Bits (continued)

15	14 13	12	11	10	9	8	7	6	5	4	3	2	1	0		
0	0 0	0	0	0	FOF[n] OFF7	FOF[n] OFF6	FOF[n] OFF5	FOF[n] OFF4	FOF[n] OFF3	FOF[n] OFF2	FOF[n] OFF1	FOF[n] OFF0	FOF[r C1			
Bit	Na	ame		Description												
15 - 10	Un	used	F	Reserved. In normal functional mode, these bits MUST be set to zero.												
9 - 2	FOF[n]	OFF7 -		Po_OFF				rafars to	the ch	annel of	feat from	origin	al frai	ma haun		
				ıry. Perm	•							_		ine bour		
1 - 0	FOF[r	n]C1 - 0	a		itted cl	hannel c	offset va					_		ine boui		
1 - 0	FOF[r	n]C1 - 0	a	ıry. Perm	itted cl	hannel c	offset valits		pend or	FOF[n]		register	rity	Positior Contro		
1 - 0	FOF[r	n]C1 - 0	a	FPo_OFF	F[n] Co	ntrol bi	offset valits Fluis	llues de	pend or [n] Width	FOF[n] Peri Chann	Of this OFF7 - 0	register	rity trol	Position		
1 - 0	FOF[r	n]C1 - 0	a	FPo_OFF FOF[n]C 1-0	itted cl	ntrol bi ata Rate Mbps)	offset value of the second of	Po_OFF e Cycle \	pend or [n] Width z clock	FOF[n] Peri Chann	OFF7 - 0 mitted lel Offset	Pola Con	rity trol	Position Contro		
1 - 0	FOF[r	n]C1 - 0	a	FOF[n]C	itted cl	pontrol binata Rate Mbps)	offset value of the value of th	Po_OFF e Cycle \	pend or [n] Width z clock z clock	FOF[n] Peri Chann 0	OFF7 - 0 mitted el Offset	Pola Con	rity trol	Position Contro		

Table 18 - FPo_OFF[n] Register (FPo_OFF[n]) Bits

Note: [n] denotes output offset frame pulse from 0 to 2.

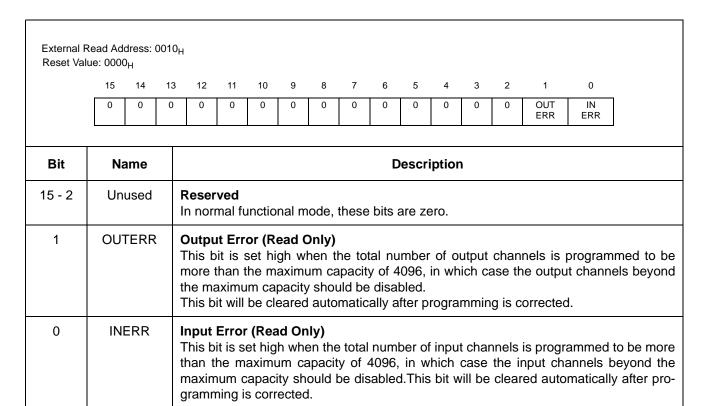


Table 19 - Internal Flag Register (IFR) Bits - Read Only

Reset	nal Read A Value: 00														
	15 14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
_	ER BER		BER F12	BER F11	BER F10	BER F9	BER F8	BER F7	BER F6	BER F5	BER F4	BER F3	BER F2	BER F1	BER F0
Bit	Na	me							Descri	ption					
15 - 0	BEI	RF[n]	If BE zero.	RF[n] i		it indi		hat BE				Ū	\	_]) is no

Table 20 - BER Error Flag Register 0 (BERFR0) Bits - Read Only

l l		Read/Writ alue: 0000 14		ess: 0001 12 BER	12 _H	10 BER	9 BER	8 BER	7 BER	6 BER	5 BER	4 BER	3 BER	2 BER	1 BER	0 BER	1
	F31		F29	F28	F27	F26	F25	F24	F23	F22	F21	F20	F19	F18	F17	F16	
Bi	t	Nan	ne						I	Descri	ption						
15 -	0	BERF	-[n]	If BE zero.	RF[n] i		, it indi						Ū	\	-]) is no) is zer	
Note:	[n] de	enotes inp	ut strea	am from	16 - 31												

Table 21 - BER Error Flag Register 1 (BERFR1) Bits - Read Only

		Read Add lue: 0000 _l		0013 _H													
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
	BER L15	BER L14	BER L13	BER L12	BER L11	BER L10	BER L9	BER L8	BER L7	BER L6	BER L5	BER L4	BER L3	BER L2	BER L1	BER L0	
Bi	t	Nam	ne						ſ	Descri	ption						
15 -	0	BERL	_[n]	If BE	RL[n] i	•	it indi				eiver of	-	-		l.		
Note:	[n] dei	notes inp	ut strea	am from	0 - 15.												

Table 22 - BER Receiver Lock Register 0 (BERLR0) Bits - Read Only

		Read Add ue: 0000 _l		0014 _H												
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	BER L31	BER L30	BER L29	BER L28	BER L27	BER L26	BER L25	BER L24	BER L23	BER L22	BER L21	BER L20	BER L19	BER L18	BER L17	BER L16
Bit	t	Nam	ne) Descri	ption					

Table 23 - BER Receiver Lock Register 1 (BERLR1) Bits - Read Only

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	STIN[n] BD2	STIN[n] BD1	STIN[n] BD0	STIN[n] SMP1	STIN[n] SMP0	STIN[n] DR3	STIN[n] DR2	STIN[n] DR1	STIN[n] DR0
Bi	it		N	lame)										
15 - 9 Unused Reserved In normal functional mode, these bits MUST be set to zero											to zero.				
8 -	6	S	STIN[n]BE)2 - (-	Input Str The binar will be de								
5 -	4	S	TIN[r	n]SM	P1 -	0	Input Da	ta Samp	ling Poi	nt Selec	tion Bits	S			
							STIN[n]S	Mbps	(16.38	ing Point 34 Mbps eams)					
							00)			3/4 point			2/4	point
							01			,	1/4 point				
							10)		2	2/4 point			4/4	point

Table 24 - Stream Input Control Register 0 - 31 (SICR0 - 31) Bits

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	STIN[n] BD2	STIN[n] BD1	STIN[n] BD0	STIN[n] SMP1	STIN[n] SMP0	STIN[n] DR3	STIN[n] DR2	STIN[n] DR1	STIN[n] DR0
_															
Bi	t		N	lame	•					D	escripti	on			
3 -	0	S	TIN[n]DR	3 - 0	ı	nput Dat	ta Rate	Selectio	n Bits:					
	3 - 0 STIN[n]DR3 - 0								STIN[n][DR3-0		Data Rate	!		
									000	0	Stre	eam Unus	sed	-	
								-	000	1	2.	.048 Mbp	S		
								-	001	0	4.	.096 Mbp	S		
									001	1	8.	.192 Mbp	s	-	
								-	010	0	16	.384 Mbp	os		
								Ī	0101 -	1111	F	Reserved		1	

Table 24 - Stream Input Control Register 0 - 31 (SICR0 - 31) Bits (continued)

15 14	13 12	11	10	9	8	7	6	5	4	3	2	1	0
0 0	0 0	STIN[n] Q3C2	STIN[n] Q3C1	STIN[n] Q3C0	STIN[n] Q2C2	STIN[n] Q2C1	STIN[n] Q2C0	STIN[n] Q1C2	STIN[n] Q1C1	STIN[n] Q1C0	STIN[n] Q0C2	STIN[n] Q0C1	STIN[n] Q0C0
Bit		Name						Desci	ription				
15 - 12		Unused		Reserve In norma		nal mod	le, thes	e bits M	IUST be	e set to	zero.		
11 - 9	STIN	V[n]Q3C2	1 8	Quadran These thas Ch24 4.096 Mb	ree bits to 31, C	are use	d to coi 63, Ch9	ntrol ST 16 to 12	7 and C	h192 to	255 for	the 2.0	
					STIN[n 2-0	-			Ope	ration			
					0x:	х			normal	operation	n		
					10	0	LS	SB of eac	ch chanr	el is rep	laced by	"0"	
					10	1				•	laced by		
					110	0	MS	SB of ea	ch chanr	nel is rep	laced by	"0"	
					11	1	MS	SB of ea	ch chanr	nel is rep	laced by	"1"	
8 - 6	STIN	l[n]Q2C2	ā	Quadran These thas Ch16 4.096 Mb	ree bits to 23, 0 ps 8.19	are use Ch32 to 32 Mbps	d to coi 47, Ch	ntrol ST 64 to 95	and C	h128 to	191 for	the 2.0	
						N[n]Q2C 2-0			Ope	ration			
						0xx			normal	operatio	n		
						100	LS	SB of eac	ch chanr	nel is rep	laced by	"0"	
						101	LS	SB of eac	ch chanr	nel is rep	laced by	"1"	
						110	M	SB of ea	ch chani	nel is rep	laced by	"0"	
												1	

Table 25 - Stream Input Quadrant Frame Register 0 - 31 (SIQFR0 - 31) Bits

Reset Value:	13 12	11	10	9	8	7	6	5	4	3	2	1	0
0 0	0 0	STIN[n] Q3C2	STIN[n] Q3C1	STIN[n] Q3C0	STIN[n] Q2C2	STIN[n] Q2C1	STIN[n] Q2C0	STIN[n] Q1C2	STIN[n] Q1C1	STIN[n] Q1C0	STIN[n] Q0C2	STIN[n] Q0C1	STIN[n] Q0C0
		Q302	QSCT	Q300	QZCZ	QZCT	Q2C0	Q102	QIOI	Q100	Q002	QUOT	Queu
Bit		Name						Descr	iption				
5 - 3	STIN	[n]Q1C2	T a	Nuadran These thr s Ch8 to .096 Mb	ee bits o 15, C	are use	ed to co 31, Ch	ntrol ST 32 to 63	and C	h64 to	127 for	the 2.0	
					ST	IN[n]Q10 2-0			Оре	eration			
						0xx			normal	operatio	n		
						100	L	SB of ea	ch chanr	nel is rep	laced by	"0"	
						101	L	SB of ea	ch chanr	nel is rep	laced by	"1"	
						110	M	SB of ea	ich chan	nel is rep	placed by	/ "0"	
						111	M	SB of ea	ich chan	nel is rep	placed by	/ "1"	
2 - 0	STIN	[n]Q0C2	T a	Nuadran These thr s Ch0 to .096 Mb	ee bits o 7, C	are use	d to co 15, Ch	ntrol ST 0 to 31	and C	ch0 to	63 for	the 2.0	
					STI	N[n]Q0C	2-0		Оре	eration			
						0xx			normal	operatio	n		
						100	L	SB of ea	ich chan	nel is rep	olaced by	/ "O"	
						101	L	SB of ea	ich chan	nel is rep	olaced by	/ "1"	
						110		ISB of ea					
						111		1SB of ea					

Table 25 - Stream Input Quadrant Frame Register 0 - 31 (SIQFR0 - 31) Bits (continued)

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	STOHZ [n]A2	STOHZ [n]A1	STOHZ [n]A0	STO[n] FA1	STO[n] FA0	STO[n] AD2	STO[n] AD1	STO[n] AD0	STO[n] DR3	STO[n] DR2	STO[n] DR1	STO[n] DR0
Bit			Na	me						Descri	iption				
15 - 1	2			used	Ros	erved									
10 1	_		One	200a		ormal fu	ınction	al mode	, these	bits M	UST be	set to	zero.		
11 - 9	9	ST	OHZ	[n]A2 - (STO	HZ Ad	ditiona	al Adva	nceme	nt Bits					
			(Valid STic	only for 0-15)	S	TOHZ[n]A2-0		.048 Mb		icement 96 Mbps s)				ancemei streams
						000				0 bit				0 bit	
						001				1/4 bit				2/4 bi	
						010 011				2/4 bit 3/4 bit				4/4 bi	
						100				4/4 bit				Reserv	ea
						101-1	11			eserved	l				
8 - 7	,	07	[O[n]	FA1 - 0	Out	put Str	oam[n	l Fracti	onal A	dvance	ment F	Rite			
0 - 1		3	ı O[ii]	A - 0		put ou	camin	j i racii				J113			
					s	STO[n]FA	1-0				6 Mbps,			Advance 34 Mbps	ment streams
						00				0				0	
						01				1/4 bit				2/4	
						10			2	2/4 bit				Reserv	ed ed
						11			;	3/4 bit					
6 - 4		ST	O[n]	AD2 - 0	The is to	put Street binary be addeduced by anceme	value d	f these	bits refe	ers to th	ne num	ber of b			•
3 - 0	3 - 0 STO[n]D			DR3 - 0	Out	put Dat	a Rate	Select	ion Bit	s					
							S	TIN[n]DI	R3 - 0		Da	ata Rate)		
								0000)			ed: STio Z driven			
								0001			2.0	48 Mbps	S		
								0010)		4.0	96 Mbps	s		
								0011			8.1	92 Mbps	S		
								0100)		16.3	384 Mbp	os		
		l			ı			0101 - 1	444			eserved			

Table 26 - Stream Output Control Register 0 - 31 (SOCR0 - 31) Bits

Externa Reset V			ddres	s: 0300 _F	_I - 031F	Н									
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	0	ST[n] BRS7	ST[n] BRS6	ST[n] BRS5	ST[n] BRS4	ST[n] BRS3	ST[n] BRS2	ST[n] BRS1	ST[n] BRS0
	ı														•
Bit	ı	Name							D	escript	ion				
15 - 8	U	Inused	i	Reser In nor		nction	nal mo	de, thes	se bits N	//UST b	e set to	zero.			
7 - 0		ST[n] RS7 -	0		nary v	/alue		re Start se bits r		the inp	ut char	inel in v	vhich th	e BER	data start
				to be t	ompa	area.									

Table 27 - BER Receiver Start Register [n] (BRSR[n]) Bits

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	ST[n] BL8	ST[n] BL7	ST[n] BL6	ST[n] BL5	ST[n] BL4	ST[n] BL3	ST[n] BL2	ST[n] BL1	ST[n] BL0
Bit Name Description															
15 - 9	U	Unused Reserved In normal functional mode, these bits MUST be set to zero.													
8 - 0 ST[n] BL8 - 0 Stream[n] BER Length Bits The binary value of these bits refers to the number of consecutive channels expected to receive the BER pattern. The maximum number of BER channels is 32, 64, 128 and 256 for the data rates of 2.048 Mbps, 4.096 Mbps, 8.192 Mbps and 16.384 Mbps respectively. The minimum number of BER channels is 1. If these bits are set to zero, no BER test will be performed.															

Table 28 - BER Receiver Length Register [n] (BRLR[n]) Bits

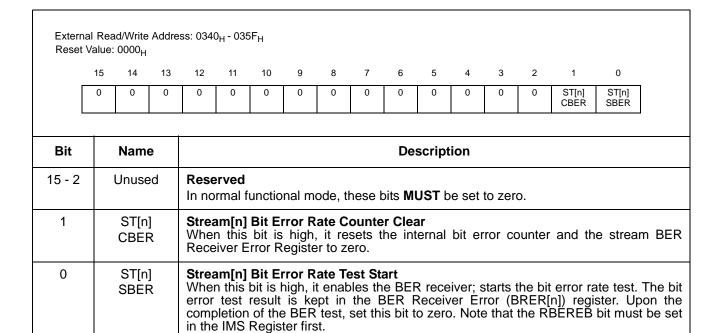


Table 29 - BER Receiver Control Register [n] (BRCR[n]) Bits

Note: [n] denotes input stream from 0 - 31

	External Read Address: 0360 _H - 037F _H Reset Value: 0000 _H												
15													
ST[n] BC15													
Bit													
15 - 0 ST[n] BC15 - 0 Stream[n] BER Count Bits (Read Only) The binary value of these bits refers to the bit error counts. When it reaches its maximum value of 0xFFFF, the value will be held and will not rollover.													
Note: [n]	Note: [n] denotes input stream from 0 - 31												

Table 30 - BER Receiver Error Register [n] (BRER[n]) Bits - Read Only

20.0 Memory

20.1 Memory Address Mappings

When A13 is high, the data or connection memory can be accessed by the microprocessor port. Bit 1 - 0 in the Control Register determine the access to the data or connection memory (CM_L or CM_H).

MSB (Note 1)				am Add (St0 - 31								nnel A (Ch0 -		s	
A13	A12	A11	A10	А9	A8	Stream [n]	Α7	A6	A5	A4	А3	A2	A1	A0	Channel [n]
1 1 1 1 1 1 1 1 1 1 	0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	0 0 0 0 0 0 0 0 1	0 0 0 0 0 1 1 1 1 1 0 0	0 0 1 1 1 0 0 1 1 1 0 0	0 1 0 1 0 1 0 1 0 0	Stream 0 Stream 1 Stream 2 Stream 3 Stream 4 Stream 5 Stream 6 Stream 7 Stream 8	0 0 0 0 0 0	0 0 0 0 0 0 0 0 0	0 0 0 0 0 0 1 1 1	0 0 0	0 0 0	0 0 0	0 0 0	0 1	Ch 0 Ch 1 Ch 30 Ch 31 (Note 2) Ch 32 Ch 33 Ch 62 Ch 63 (Note 3)
1 1	1	1	1	1	0	Stream 30 Stream 31	0			1	1		1 1	1 0	Ch 127 (Note 4)

Note 1: A13 must be high for access to data and connection memory positions. A13 must be low to access internal registers.

Table 31 - Address Map for Memory Locations (A13 = 1)

Note 2: Channels 0 to 31 are used when serial stream is at 2.048 Mbps.

Note 3: Channels 0 to 63 are used when serial stream is at 4.096 Mbps.

Note 4: Channels 0 to 127 are used when serial stream is at 8.192 Mbps.

Note 5: Channels 0 to 255 are used when serial stream is at 16.384 Mbps.

20.2 Connection Memory Low (CM_L) Bit Assignment

When the CMM bit (bit 0) in the connection memory low is zero, the per-channel transmission is set to the normal channel-switching. The connection memory low bit assignment for the channel transmission mode is shown in Table 32 on page 57.

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
UA EN	V/C	SSA 4	SSA 3	SSA 2	SSA 1	SSA 0	SCA 7	SCA 6	SCA 5	SCA 4	SCA 3	SCA 2	SCA 1	SCA 0	CMM =0
Bit	N	ame							Descri	ption					
15	U	AEN	Wh tion Wh	Conversion between μ -law and A-law Enable When this bit is low, normal switch without μ -law/A-law conversion. Connection memory high will be ignored. When this bit is high, switch with μ -law/A-law conversion, and connection memory high controls the conversion method.											
14	,	V/C	Wh sta Wh var	Variable/Constant Delay Control When this bit is low, the output data for this channel will be taken from constant delay memory. When this bit is set to high, the output data for this channel will be taken from variable delay memory. Note that VAREN must be set in Control Register first.											
13 - 9	SS	A4 - 0		urce S e bina				bits r	eprese	ents th	e inpu	ıt strea	am nur	mber.	
8 - 1	SC	A7 - 0	Source Channel Address The binary value of these 8 bits represents the input channel number.												
0	CM	CMM = 0													
Note: For	prope	er μ-lav	w/A-law	conve	rsion, t	he CM_	_H bits	should	be set	before l	Bit 15 (UAEN I	bit) is s	et to hi	gh.

Table 32 - Connection Memory Low (CM_L) Bit Assignment when CMM = 0

When CMM is one, the device is programmed to perform one of the special per-channel transmission modes. Bits PCC0 and PCC1 from connection memory are used to select the per-channel tristate, message or BER test mode as shown in Table 33 on page 58.

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
UA EN	0	0	0	0	MSG 7	MSG 6	MSG 5	MSG 4	MSG 3	MSG 2	MSG 1	MSG 0	PCC 1	PCC 0	CMM =1
Bit		Nam	e						De	scripti	ion				
15		UAE	N	Wh tion Wh	en this n mem nen this	s bit is ory hig s bit is	low, m h will l high, r	essage be igno nessag	e mode red. ge mod	e has n le has	•	w/A-lav A-law c	v conve	ersion.	nly) Connec- nd con-
14 - 11	l	Jnus	ed		serve normal	-	onal m	ode, th	ese bi	ts MUS	ST be s	set to z	ero.		
10 - 3	N	ISG7	- 0	8-b	Message Data Bits 8-bit data for the message mode. Not used in the per-channel tristate and BER test modes.										
2 - 1	Р	CC1	- 0	_	r-Char ese tw	-			rrespo	nding (entry's	value (on the	STio s	tream.
							PC C1	PC C0	C	hannel	Output	Mode			
							0	0	F	Per Cha	annel Tr	istate			
							0	1		Mess	age Mo	ode			
							1	0		BER	Test Mo	ode			
	1 1 Reserved														
0	0 CMM = 1 Connection Memory Mode = 1 If this is high, the connection memory is in the per-channel control mode which is per-channel tristate, per-channel message mode or per-channel BER mode. Note: For proper μ-law/A-law conversion, the CM_H bits should be set before Bit 15 (UAEN bit) is set to high.														
Note: For	prop	er μ-	law/A-	law c	onversi	on, the	CM_H	oits shou	ıld be se	et befor	e Bit 15	(UAEN	bit) is s	et to hig	ıh.

Table 33 - Connection Memory Low (CM_L) Bit Assignment when CMM = 1

20.3 Connection Memory High (CM H) Bit Assignment

Connection memory high provides the detailed information required for μ -law and A-law conversion. ICL and OCL bits describe the Input Coding Law and the Output Coding Law, respectively. They are used to select the expected PCM coding laws for the connection, on the TDM inputs, and on the TDM outputs. The \overline{V}/D bit is used to select the class of coding law. If the \overline{V}/D bit is cleared (to select a voice connection), the ICL and OCL bits select between A-law and μ -law specifications related to G.711 voice coding. If the \overline{V}/D bit is set (to select a data connection), the ICL and OCL bits select between various bit inverting protocols. These coding laws are illustrated in the following table. If the ICL is different than the OCL, all data bytes passing through the switch on that particular connection are translated between the indicated laws. If the ICL and the OCL are the same, no coding law translation is performed. The ICL, the OCL bits and \overline{V}/D bit only have an effect on PCM code translations for constant delay connections, variable delay connections and per-channel message mode.

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0							
0	0	0	0	0	0	0	0	0	0	0	V/D	ICL 1	ICL 0	OCL 1	OCI 0							
Bit	N	ame							Descri	ption												
15 - 5	Un	used		serve	ed al funct	ional	mode,	these	bits N	IUST	be set	to zer	0.									
4 V/D Voice/Data Control When this bit is low, the corresponding channel is for voice. When this bit is high, the corresponding channel is for data. 3 - 2 ICL1 - 0 Input Coding Law.																						
3 - 2	ICI	_1 - 0	Inp	ut Co	oding l	Law.																
					ICI 1 0		ICL1-0			Input Coding Law										Input Coding Law		
					ICL1-0	For Voice $(\overline{V}/D \text{ bit } = 0)$ For Data $(\overline{V}/D \text{ bit } = 1)$					For Voice (\overline{V}/D bit = 0) For Data (\overline{V}/D bit = 1)		, , ,		1)							
					00							No cod	de									
					01		CCIT	Γ.ITU μ	law			ABI										
					10		A-law w/o ABI Inverted ABI μ-law w/o Magnitude All Bits Inverted															
					11	ļ		o Mag versior			All	Bits Inv	erted									
1 - 0	ОС	L1 - 0	Ou	tput (Coding	g Law	·															
									Outpu	ıt Codi	ng Law	,										
OCL1-0 For Voice $(\overline{V}/D \text{ bit} = 0)$ For Data $(\overline{V}/D \text{ bit} = 1)$																						
			00 CCITT.ITU A-law No code																			
					01		CCIT	T.ITU	μ-law			ABI										
					10		A-la	aw w/o	ABI		In	verted	ABI									
					11		μ-law \ I	w/o Ma nversio		е	All E	Bits Inv	erted									

Table 34 - Connection Memory High (CM_H) Bit Assignment

Note 2: Refer to G.711 standard for detail information of different laws.

21.0 DC Parameters

Absolute Maximum Ratings*

	Parameter	Symbol	Min.	Max.	Units
1	I/O Supply Voltage	V _{DD_IO}	-0.5	5.0	V
2	Core Supply Voltage	V _{DD_CORE}	-0.5	2.5	V
3	Input Voltage	V _{I_3V}	-0.5	V _{DD} + 0.5	V
4	Input Voltage (5 V-tolerant inputs)	V_{I_5V}	-0.5	7.0	V
5	Continuous Current at Digital Outputs	Io		15	mA
6	Package Power Dissipation	P _D		1.5	W
7	Storage Temperature	T _S	- 55	+125	°C

^{*} Exceeding these values may cause permanent damage. Functional operation under these conditions is not implied.

$\textbf{Recommended Operating Conditions -} \ \ \text{Voltages are with respect to ground (V_{SS}) unless otherwise stated.}$

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units
1	Operating Temperature	T _{OP}	-40	25	+85	°C
2	Positive Supply	V_{DD_IO}	3.0	3.3	3.6	V
3	Positive Supply	V_{DD_CORE}	1.71	1.8	1.89	V
4	Input Voltage	VI	0	3.3	V_{DD_IO}	٧
5	Input Voltage on 5 V-Tolerant Inputs	$V_{I_{-5}V}$	0	5.0	5.5	V

[‡] Typical figures are at 25°C and are for design aid only: not guaranteed and not subject to production testing.

DC Electrical Characteristics[†] - Voltages are with respect to ground (V_{ss}) unless otherwise stated.

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions
1	Supply Current - V _{DD_CORE}	I _{DD_CORE}			130	mA	
2	Supply Current - V _{DD_IO}	I _{DD_IO}			70	mA	C _L = 30 pF
3	Input High Voltage	V _{IH}	2.0			V	
4	Input Low Voltage	V _{IL}			0.8	V	
5	Input Leakage (input pins) Input Leakage (bi-directional pins)	I _{IL} I _{BL}			5 5	μA μA	0≤ <v<sub>IN≤V_{DD_IO} See Note 1</v<sub>
6	Weak Pullup Current	I _{PU}		-33		μΑ	Input at 0V
7	Weak Pulldown Current	I _{PD}		33		μΑ	Input at V _{DD_IO}
8	Input Pin Capacitance	C _I		3		pF	
9	Output High Voltage	V _{OH}	2.4			V	I _{OH} = 8 mA
10	Output Low Voltage	V _{OL}			0.4	V	I _{OL} = 8 mA
11	Output High Impedance Leakage	I _{OZ}			5	μΑ	0 < V < V _{DD}
12	Output Pin Capacitance	Co		5	10	pF	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

^{*} Note 1: Maximum leakage on pins (output or I/O pins in high impedance state) is over an applied voltage (V_{IN}).

22.0 AC Parameters

AC Electrical Characteristics[†] - Timing Parameter Measurement Voltage Levels

	Characteristics	Sym.	Level	Units	Conditions
1	CMOS Threshold	V_{CT}	0.5 V _{DD_IO}	V	
2	Rise/Fall Threshold Voltage High	V_{HM}	0.7 V _{DD_IO}	V	
3	Rise/Fall Threshold Voltage Low	V_{LM}	0.3 V _{DD_IO}	V	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

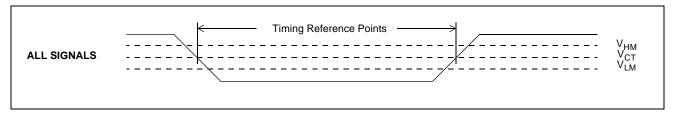


Figure 19 - Timing Parameter Measurement Voltage Levels

AC Electrical Characteristics[†] - Motorola Non-Multiplexed Bus Mode - Read Access

	Characteristics	Sym	Min.	Typ. [‡]	Max.	Units	Test Conditions ²
1	CS de-asserted time	t _{CSD}	15			ns	
2	DS de-asserted time	t _{DSD}	15			ns	
3	CS setup to DS falling	t _{CSS}	0			ns	
4	R/W setup to DS falling	t _{RWS}	10			ns	
5	Address setup to DS falling	t _{AS}	5			ns	
6	CS hold after DS rising	t _{CSH}	0			ns	
7	R/W hold after DS rising	t _{RWH}	0			ns	
8	Address hold after DS rising	t _{AH}	0			ns	
9	Data setup to DTA Low	t _{DS}	8			ns	C _L = 50 pF
10	Data hold after DS rising	t _{DHZ}			8	ns	$C_L = 50 \text{ pF}, R_L = 1 \text{ K}$ (Note 1)
11	Acknowledgement delay time. From DS low to DTA low: Registers Memory	t _{AKD}			75 185	ns ns	C _L = 50 pF C _L = 50 pF
12	Acknowledgement hold time. From DS high to DTA high	t _{AKH}	4		12	ns	$C_L = 50 \text{ pF}, R_L = 1 \text{ K}$ (Note 1)
13	DTA drive high to HiZ	t _{AKZ}			8	ns	

Note 1: High impedance is measured by pulling to the appropriate rail with R_L, with timing corrected to cancel time taken to discharge C_L.

Note 2: A delay of 500 μs to 2 ms (see Section 13.2 on page 33) must be applied before the first microprocessor access is performed after the RESET pin is set high.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

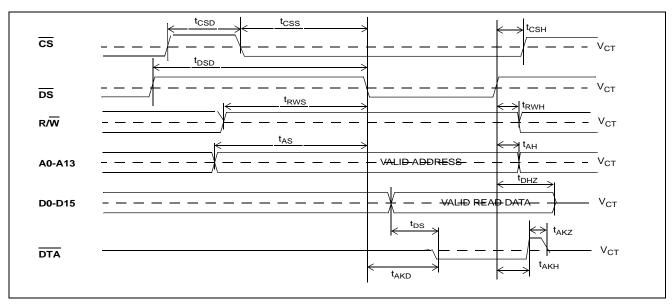


Figure 20 - Motorola Non-Multiplexed Bus Timing - Read Access

[†] Characteristics are over recommended operating conditions unless otherwise stated.

AC Electrical Characteristics[†] - Motorola Non-Multiplexed Bus Mode - Write Access

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions ²
1	CS de-asserted time	t _{CSD}	15			ns	
2	DS de-asserted time	t _{DSD}	15			ns	
3	CS setup to DS falling	t _{CSS}	0			ns	
4	R/W setup to DS falling	t _{RWS}	10			ns	
5	Address setup to DS falling	t _{AS}	5			ns	
6	Data setup to DS falling	t _{DS}	0			ns	$C_L = 50 \text{ pF}$
7	CS hold after DS rising	t _{CSH}	0			ns	
8	R/W hold after DS rising	t _{RWH}	0			ns	
9	Address hold after DS rising	t _{AH}	0			ns	
10	Data hold from DS rising	t _{DH}	5			ns	$C_L = 50 \text{ pF}, R_L = 1K$ (Note 1)
11	Acknowledgement delay time. From DS low to DTA low: Registers Memory	t _{AKD}			55 150	ns ns	C _L = 50 pF C _L = 50 pF
12	Acknowledgement hold time. From DS high to DTA high	t _{AKH}	4		12	ns	$C_L = 50 \text{ pF}, R_L = 1K$ (Note 1)
13	DTA drive high to HiZ	t _{AKZ}			8	ns	

Note 1: High impedance is measured by pulling to the appropriate rail with R_L, with timing corrected to cancel time taken to discharge C_L.

Note 2: A delay of 500 μs to 2 ms (see Section 13.2 on page 33) must be applied before the first microprocessor access is performed after the RESET pin is set high.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

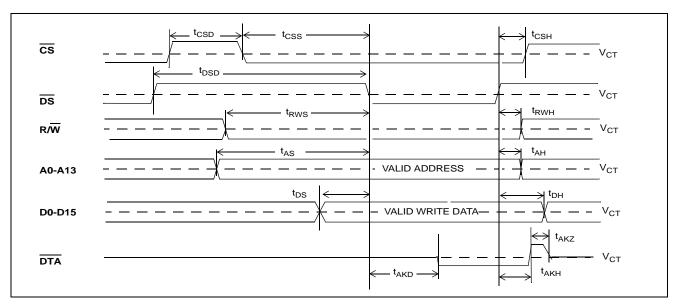


Figure 21 - Motorola Non-Multiplexed Bus Timing - Write Access

[†] Characteristics are over recommended operating conditions unless otherwise stated.

AC Electrical Characteristics[†] - Intel Non-Multiplexed Bus Mode - Read Access

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions ²
1	CS de-asserted time	t _{CSD}	15			ns	
2	RD setup to CS falling	t _{RS}	10			ns	
3	WR setup to CS falling	t _{WS}	10			ns	
4	Address setup to CS falling	t _{AS}	5			ns	
5	RD hold after CS rising	t _{RH}	0			ns	
6	WR hold after CS rising	t_{WH}	0			ns	
7	Address hold after CS rising	t _{AH}	0			ns	
8	Data setup to RDY high	t _{DS}	8			ns	C _L = 50 pF
9	Data hold after CS rising	t _{CSZ}	7			ns	C _L = 50 pF, R _L = 1 K (Note 1)
10	Acknowledgement delay time. From CS low to RDY high: Registers	t _{AKD}			175	ns	0 50 5
	Memory				185	ns	$C_L = 50 \text{ pF}$ $C_L = 50 \text{ pF}$
11	Acknowledgement hold time. From CS high to RDY low	t _{AKH}	4		12	ns	$C_L = 50 \text{ pF}, R_L = 1 \text{ K}$ (Note 1)
12	RDY drive low to HiZ	t _{AKZ}			8	ns	

Note 1: High impedance is measured by pulling to the appropriate rail with R_L, with timing corrected to cancel time taken to discharge C_L.

Note 2: A delay of 500 μs to 2 ms (see Section 13.2 on page 33) must be applied before the first microprocessor access is performed after the RESET pin is set high.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

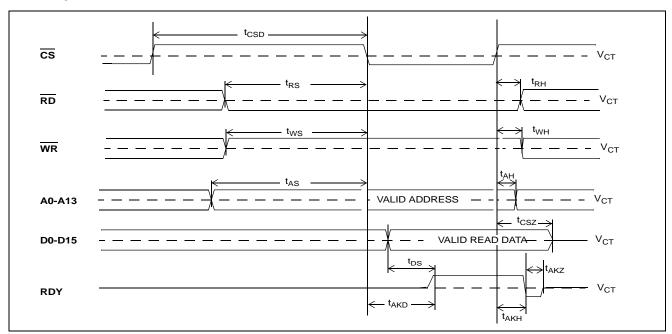


Figure 22 - Intel Non-Multiplexed Bus Timing - Read Access

[†] Characteristics are over recommended operating conditions unless otherwise stated.

AC Electrical Characteristics[†] - Intel Non-Multiplexed Bus Mode - Write Access

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions ²
1	CS de-asserted time	t _{CSD}	15			ns	
2	WR setup to CS falling	t _{WS}	10			ns	
3	RD setup to CS falling	t _{RS}	10			ns	
4	Address setup to CS falling	t _{AS}	5			ns	
5	Data setup to CS falling	t _{DS}	0			ns	C _L = 50 pF
6	WR hold after CS rising	t _{WH}	0			ns	
7	RD hold after CS rising	t _{RH}	0			ns	
8	Address hold after CS rising	t _{AH}	10			ns	
9	Data hold after CS rising	t _{DH}	5			ns	$C_L = 50 \text{ pF}, R_L = 1K$ (Note 1)
10	Acknowledgement delay time. From CS low to RDY high: Registers Memory	t _{AKD}			55 150	ns ns	C _L = 50 pF C _L = 50 pF
11	Acknowledgement hold time. From CS high to RDY low	t _{AKH}	4		12	ns	$C_L = 50 \text{ pF}, R_L = 1K$ (Note 1)
12	RDY drive low to HiZ	t _{AKZ}			8	ns	

Note 1: High impedance is measured by pulling to the appropriate rail with R_L , with timing corrected to cancel time taken to discharge C_L .

Note 2: A delay of 500 μs to 2 ms (Section 13.2 on page 33) must be applied before the first microprocessor access is performed after the RESET pin is set high.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

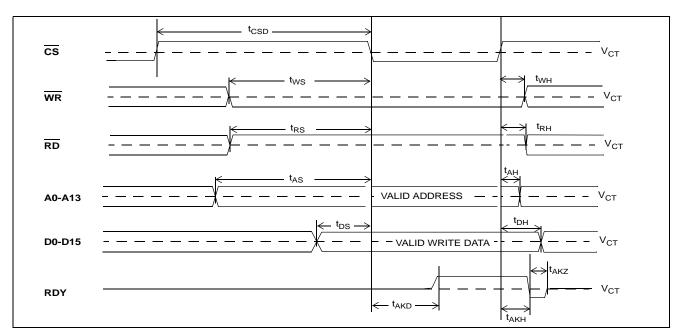


Figure 23 - Intel Non-Multiplexed Bus Timing - Write Access

[†] Characteristics are over recommended operating conditions unless otherwise stated.

AC Electrical Characteristics[†] - JTAG Test Port Timing

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Notes
1	TCK Clock Period	t _{TCKP}	100			ns	
2	TCK Clock Pulse Width High	t _{TCKH}	20			ns	
3	TCK Clock Pulse Width Low	t _{TCKL}	20			ns	
4	TMS Set-up Time	t _{TMSS}	10			ns	
5	TMS Hold Time	t _{TMSH}	10			ns	
6	TDi Input Set-up Time	t _{TDIS}	20			ns	
7	TDi Input Hold Time	t _{TDIH}	60			ns	
8	TDo Output Delay	t _{TDOD}			30	ns	$C_{L} = 30 \text{ pF}$
9	TRST pulse width	t _{TRSTW}	200			ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

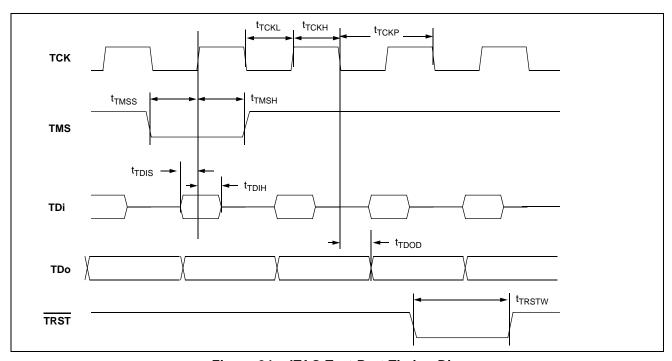


Figure 24 - JTAG Test Port Timing Diagram

AC Electrical Characteristics[†] - FPi and CKi Timing when CKIN1-0 bits = 00 (16.384 MHz)

	Characteristic	Sym.	Min.	Typ. [‡]	Max.	Units	Notes
1	FPi Input Frame Pulse Width	t _{FPIW}	40	61	115	ns	
2	FPi Input Frame Pulse Setup Time	t _{FPIS}	20			ns	
3	FPi Input Frame Pulse Hold Time	t _{FPIH}	20			ns	
4	CKi Input Clock Period	t _{CKIP}	55	61	67	ns	
5	CKi Input Clock High Time	t _{CKIH}	27		34	ns	
6	CKi Input Clock Low Time	t _{CKIL}	27		34	ns	
7	CKi Input Clock Rise/Fall Time	t _r CKi, t _f CKi			3	ns	
8	CKi Input Clock Cycle to Cycle Variation	t _{CVC}	0		20	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

AC Electrical Characteristics[†] - FPi and CKi Timing when CKIN1-0 bits = 01 (8.192 MHz)

	Characteristic	Sym.	Min.	Typ. [‡]	Max.	Units	Notes
1	FPi Input Frame Pulse Width	t _{FPIW}	90	122	220	ns	
2	FPi Input Frame Pulse Setup Time	t _{FPIS}	45			ns	
3	FPi Input Frame Pulse Hold Time	t _{FPIH}	45			ns	
4	CKi Input Clock Period	t _{CKIP}	110	122	135	ns	
5	CKi Input Clock High Time	t _{CKIH}	55		69	ns	
6	CKi Input Clock Low Time	t _{CKIL}	55		69	ns	
7	CKi Input Clock Rise/Fall Time	t _r CKi, t _f CKi			3	ns	
8	CKi Input Clock Cycle to Cycle Variation	t _{CVC}	0		20	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

AC Electrical Characteristics † - FPi and CKi Timing when CKIN1-0 bits = 10 (4.096 MHz)

	Characteristic	Sym.	Min.	Typ. [‡]	Max.	Units	Notes
1	FPi Input Frame Pulse Width	t _{FPIW}	90	244	420	ns	
2	FPi Input Frame Pulse Setup Time	t _{FPIS}	110			ns	
3	FPi Input Frame Pulse Hold Time	t _{FPIH}	110			ns	
4	CKi Input Clock Period	t _{CKIP}	220	244	270	ns	
5	CKi Input Clock High Time	t _{CKIH}	110		135	ns	
6	CKi Input Clock Low Time	t _{CKIL}	110		135	ns	
7	CKi Input Clock Rise/Fall Time	t _r CKi, t _f CKi			3	ns	
8	CKi Input Clock Cycle to Cycle Variation	t _{CVC}	0		20	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

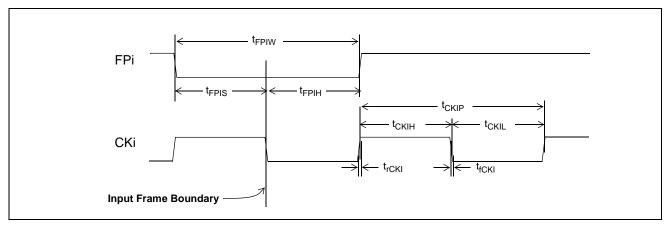


Figure 25 - Frame Pulse Input and Clock Input Timing Diagram (ST-BUS)

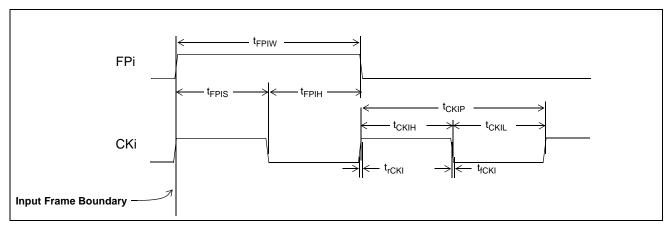


Figure 26 - Frame Pulse Input and Clock Input Timing Diagram (GCI-Bus)

AC Electrical Characteristics[†] - ST-BUS/GCI-Bus Input Timing

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Test Conditions
1	STi Setup Time						
	2.048 Mbps 4.096 Mbps 8.192 Mbps 16.384 Mbps	t _{SIS2} t _{SIS4} t _{SIS8} t _{SIS16}	5 5 5 5			ns ns ns ns	
2	STi Hold Time 2.048 Mbps 4.096 Mbps 8.192 Mbps 16.384 Mbps	t _{SIH2} t _{SIH4} t _{SIH8} t _{SIH16}	8 8 8			ns ns ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

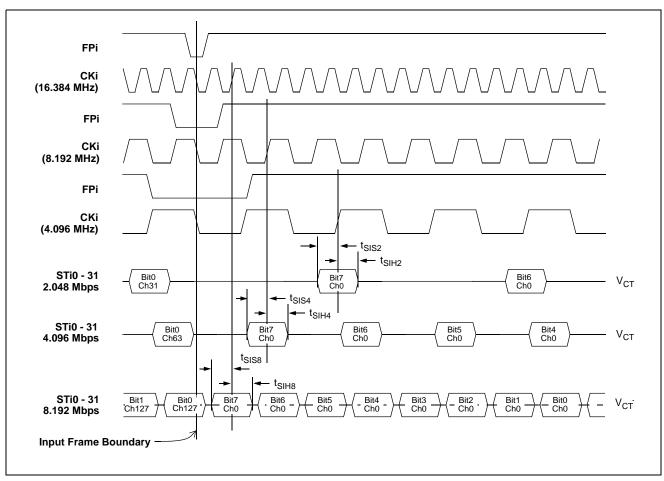


Figure 27 - ST-BUS Input Timing Diagram when Operated at 2 Mbps, 4 Mbps, 8 Mbps

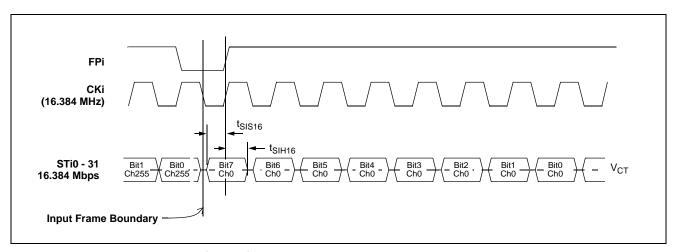


Figure 28 - ST-BUS Input Timing Diagram when Operated at 16 Mbps

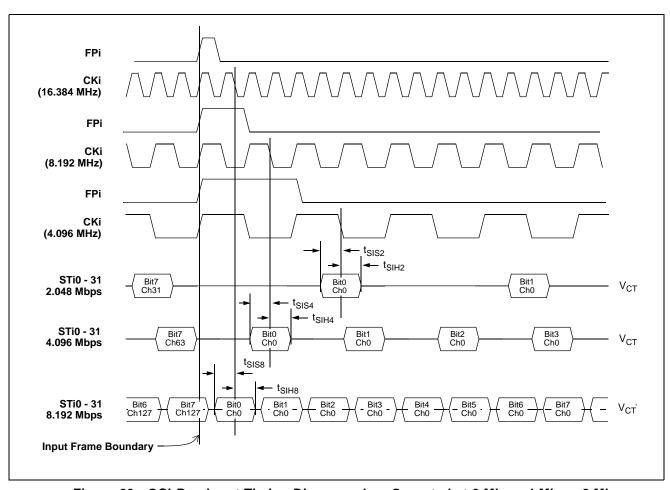


Figure 29 - GCI-Bus Input Timing Diagram when Operated at 2 Mbps, 4 Mbps, 8 Mbps

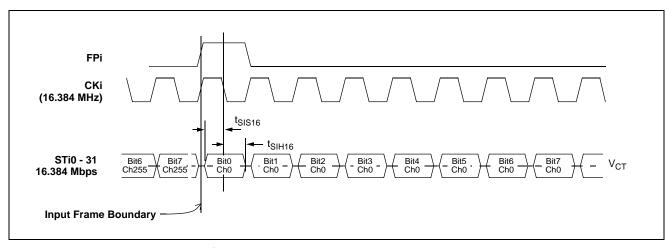


Figure 30 - GCI-Bus Input Timing Diagram when Operated at 16 Mbps

AC Electrical Characteristics[†] - ST-BUS/GCI-Bus Output Timing

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Test Conditions
1	STio Delay - Active to Active						C _L = 30 pF
	@2.048 Mbps @4.096 Mbps @8.192 Mbps @16.384 Mbps	t _{SOD2} t _{SOD4} t _{SOD8} t _{SOD16}	0 0 0 0		6 6 6	ns ns ns ns	Multiplied Clock Mode
	@2.048 Mbps @4.096 Mbps @8.192 Mbps @16.384 Mbps	t _{SOD2} t _{SOD4} t _{SOD8} t _{SOD16}	-6 -6 -6 -6		0 0 0	ns ns ns ns	Divided Clock Mode

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

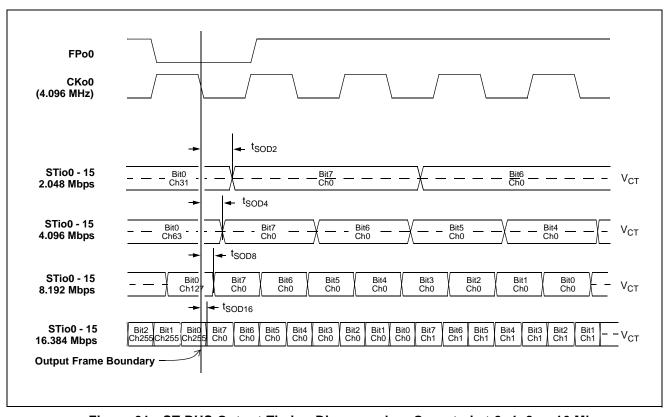


Figure 31 - ST-BUS Output Timing Diagram when Operated at 2, 4, 8 or 16 Mbps

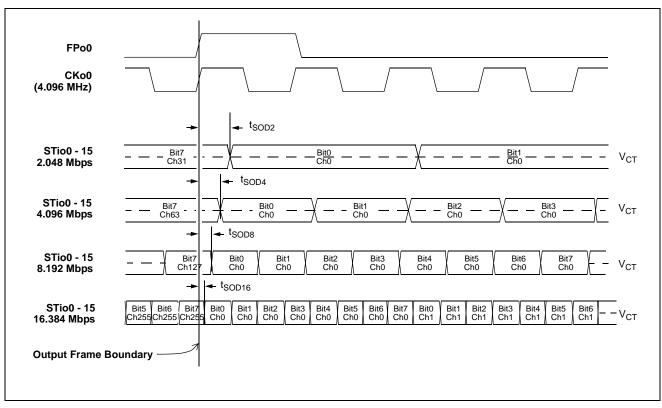


Figure 32 - GCI-Bus Output Timing Diagram when Operated at 2, 4, 8 or 16 Mbps

AC Electrical Characteristics[†] - ST-BUS/GCI-Bus Output Tristate Timing

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Test Conditions [*]
1	STio Delay - Active to High-Z	t _{DZ}	-3 -8		7	ns	Multiplied Clock Mode Divided Clock Mode
			-0		0	ns	Divided Clock Mode
2	STio Delay - High-Z to Active	t_{ZD}	-3		7	ns	Multiplied Clock Mode
	-		-8		0	ns	Divided Clock Mode
3	Output Drive Enable (ODE) Delay - High-Z to Active	t _{ZD_ODE}			77	ns	Multiplied Clock Mode
	CKi @ 4.096MHz				260	ns	Divided Clock Mode
	CKi @ 8.192MHz				138	ns	
	CKi @ 16.384MHz				77	ns	
4	Output Drive Enable (ODE) Delay	t _{DZ_ODE}					_
	- Active to High-Z				77	ns	Multiplied Clock Mode
						ns	
	CKi @ 4.096MHz				260	ns	Divided Clock Mode
	CKi @ 8.192MHz				138		
	CKi @ 16.384MHz				77		

[†] Characteristics are over recommended operating conditions unless otherwise stated.

^{*} Test condition is $R_L = 1 \text{ k}$, $C_L = 30 \text{ pF}$; high impedance is measured by pulling to the appropriate rail with R_L , with timing corrected to cancel the time taken to discharge C_L .

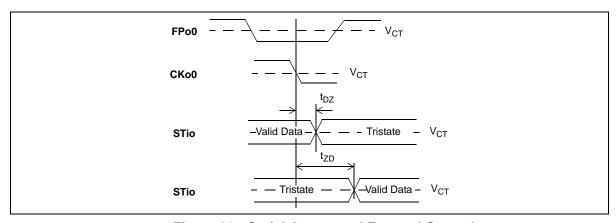


Figure 33 - Serial Output and External Control

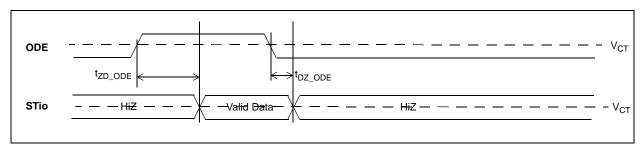


Figure 34 - Output Drive Enable (ODE)

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

AC Electrical Characteristics[†] - Input/Output Frame Boundary Alignment

	Characteristic	Sym.	Min.	Typ. [‡]	Max.	Units	Notes
1	Input and Output Frame Offset in Divided Clock Mode	^t FBOS	5		13	ns	
2	Input and Output Frame Offset in Multiplied Clock Mode	^t FBOS	2		10	ns	Input reference jitter is equal to zero.

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

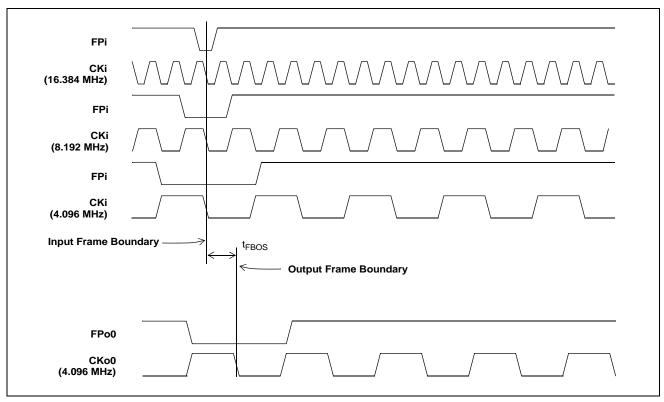


Figure 35 - Input and Output Frame Boundary Offset

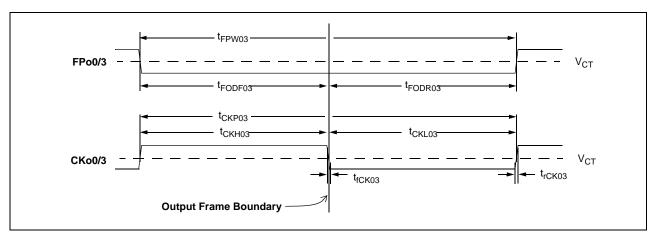


Figure 36 - FPo0/3 and CKo0/3 Timing Diagram

AC Electrical Characteristics[†] - FPo0/CKo0 and FPo3/CKo3 (4.096 MHz) Timing for Divided Clock Mode and Multiplied Clock Mode with Less than 10 ns of Cycle to Cycle Variation on CKi

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Notes
1	FPo0 Output Pulse Width	t _{FPW03}	239	244	249	ns	
2	FPo0 Output Delay from the FPo0 falling edge to the output frame boundary	t _{FODF03}	117		127	ns	$C_L = 30 pF$
3	FPo0 Output Delay from the output frame boundary to the FPo0 rising edge	t _{FODR03}	117		127	ns	
4	CKo0 Output Clock Period	t _{CKP03}	239	244	249	ns	
5	CKo0 Output High Time	t _{CKH03}	117		127	ns	$C_L = 30 pF$
6	CKo0 Output Low Time	t _{CKL03}	117		127	ns	
7	CKo0 Output Rise/Fall Time	t _{rCK03} , t _{fCK03}			5	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

AC Electrical Characteristics[†] - FPo0/CKo0 and FPo3/CKo3 (4.096 MHz) Timing for Multiplied Clock Mode with More than 10 ns of Cycle to Cycle Variation on CKi

	Characteristic	Sym.	Min.	Typ. [‡]	Max.	Units	Notes
1	FPo0 Output Pulse Width	t _{FPW03}	218	244	270	ns	
2	FPo0 Output Delay from the FPo0 falling edge to the output frame boundary	t _{FODF03}	117		127	ns	$C_L = 30 pF$
3	FPo0 Output Delay from the output frame boundary to the FPo0 rising edge	t _{FODR03}	97		146	ns	
4	CKo0 Output Clock Period	t _{CKP03}	218	244	270	ns	
5	CKo0 Output High Time	t _{CKH03}	117		127	ns	$C_L = 30 pF$
6	CKo0 Output Low Time	t _{CKL03}	97		146	ns	
7	CKo0 Output Rise/Fall Time	t_{rCK03}, t_{fCK03}			5	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

[†] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

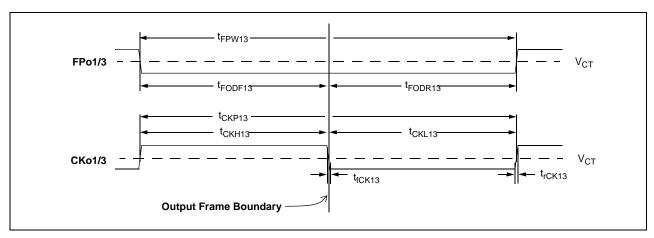


Figure 37 - FPo1/3 and CKo1/3 Timing Diagram

AC Electrical Characteristics[†] - FPo1/CKo1 and FPo3/CKo3 (8.192 MHz) Timing for Divided Clock Mode and Multiplied Clock Mode with Less than 10 ns of Cycle to Cycle Variation on CKi

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Notes
1	FPo1 Output Pulse Width	t _{FPW13}	117	122	127	ns	
2	FPo1 Output Delay from the FPo1 falling edge to the output frame boundary	t _{FODF13}	56		66	ns	$C_L = 30 pF$
3	FPo1 Output Delay from the output frame boundary to the FPo1 rising edge	t _{FODR13}	56		66	ns	
4	CKo1 Output Clock Period	t _{CKP13}	117	122	127	ns	
5	CKo1 Output High Time	t _{CKH13}	56		66	ns	$C_L = 30 pF$
6	CKo1 Output Low Time	t _{CKL13}	56		66	ns	
7	CKo1 Output Rise/Fall Time	t _{rCK13} , t _{fCK13}			5	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

AC Electrical Characteristics[†] - FPo1/CKo1 and FPo3/CKo3 (8.192 MHz) Timing for Multiplied Clock Mode with More than 10 ns of Cycle to Cycle Variation on CKi

	Characteristic	Sym.	Min.	Typ. [‡]	Max.	Units	Notes
1	FPo1 Output Pulse Width	t _{FPW13}	106	122	127	ns	
2	FPo1 Output Delay from the FPo1 falling edge to the output frame boundary	t _{FODF13}	56		66	ns	$C_L = 30 pF$
3	FPo1 Output Delay from the output frame boundary to the FPo1 rising edge	t _{FODR13}	46		66	ns	
4	CKo1 Output Clock Period	t _{CKP13}	106	122	148	ns	
5	CKo1 Output High Time	t _{CKH13}	46		87	ns	$C_L = 30 pF$
6	CKo1 Output Low Time	t _{CKL13}	46		66	ns	
7	CKo1 Output Rise/Fall Time	t _{rCK13} , t _{fCK13}			5	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

[†] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

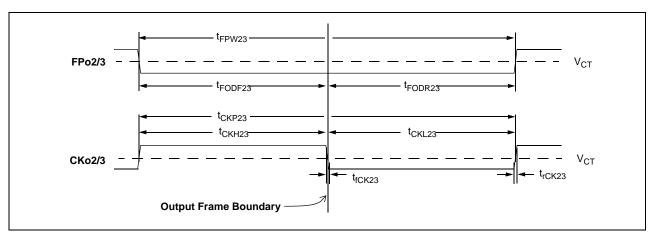


Figure 38 - FPo2/3 and CKo2/3 Timing Diagram

AC Electrical Characteristics[†] - FPo2/CKo2 and FPo3/CKo3 (16.384 MHz) Timing for Divided Clock Mode and Multiplied Clock Mode with Less than 10 ns of Cycle to Cycle Variation on CKi

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Notes
1	FPo2 Output Pulse Width	t _{FPW23}	56	61	66	ns	
2	FPo2 Output Delay from the FPo1 falling edge to the output frame boundary	t _{FODF23}	25		36	ns	$C_L = 30 pF$
3	FPo2 Output Delay from the output frame boundary to the FPo1 rising edge	t _{FODR23}	25		36	ns	
4	CKo2 Output Clock Period	t _{CKP23}	56	61	66	ns	
5	CKo2 Output High Time	t _{CKH23}	25		36	ns	$C_L = 30 pF$
6	CKo2 Output Low Time	t _{CKL23}	25		36	ns	
7	CKo2 Output Rise/Fall Time	t _{rCK23} , t _{fCK23}			5	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

AC Electrical Characteristics[†] - FPo2/CKo2 and FPo3/CKo3 (16.384 MHz) Timing for Multiplied Clock Mode with More than 10 ns of Cycle to Cycle Variation on CKi

	Cycle to Cycle variation on Ott						
	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Notes
1	FPo2 Output Pulse Width	t _{FPW23}	56	61	66	ns	
2	FPo2 Output Delay from the FPo2 falling edge to the output frame boundary	t _{FODF23}	25		36	ns	$C_L = 30 pF$
3	FPo2 Output Delay from the output frame boundary to the FPo1 rising edge	t _{FODR23}	25		36	ns	
4	CKo2 Output Clock Period	t _{CKP2}	47	61	76	ns	
5	CKo2 Output High Time	t _{CKH23}	17		43	ns	$C_L = 30 pF$
6	CKo2 Output Low Time	t _{CKL23}	17		43	ns	
7	CKo2Output Rise/Fall Time	t _{rCK23} , t _{fCK23}			5	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

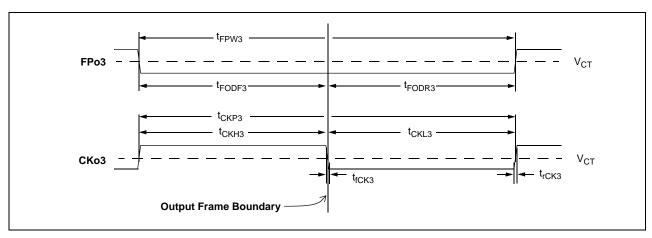


Figure 39 - FPo3 and CKo3 Timing Diagram (32.768 MHz)

AC Electrical Characteristics[†] - FPo3/CKo3 (32.768 MHz) Timing for Divided Clock Mode and Multiplied Clock Mode with Less than 10 ns of Cycle to Cycle Variation on CKi

	Characteristic	Sym.	Min.	Typ. [‡]	Max.	Units	Notes
1	FPo3 Output Pulse Width	t _{FPW3}	27	30.5	34	ns	
2	FPo3 Output Delay from the FPo1 falling edge to the output frame boundary	t _{FODF3}	10		18	ns	$C_L = 30 pF$
3	FPo3 Output Delay from the output frame boundary to the FPo3 rising edge	t _{FODR3}	12		21	ns	
4	CKo3 Output Clock Period	t _{CKP3}	27	30.5	34	ns	
5	CKo3 Output High Time	t _{CKH3}	12		19	ns	$C_L = 30 pF$
6	CKo3 Output Low Time	t _{CKL3}	12		19	ns	
7	CKo3 Output Rise/Fall Time	t _{rCK3} , t _{fCK3}			5	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

AC Electrical Characteristics[†] - FPo3/CKo3 (32.768 MHz) Timing for Multiplied Clock Mode with More than 10 ns of Cycle to Cycle Variation on CKi

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Notes
1	FPo3 Output Pulse Width	t _{FPW3}	27	30.5	34	ns	
2	2 FPo3 Output Delay from the FPo1 falling edge to the output frame boundary		12		19	ns	$C_L = 30 pF$
3	FPo3 Output Delay from the output frame boundary to the FPo1 rising edge	t _{FODR3}	12		19	ns	
4	CKo3 Output Clock Period	t _{CKP3}	17	30.5	44	ns	
5	CKo3 Output High Time	t _{CKH3}	5		29	ns	$C_L = 30 pF$
6	CKo3 Output Low Time	t _{CKL3}	12		18	ns	
7	CKo3 Output Rise/Fall Time	t _{rCK3} , t _{fCK3}			5	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

AC Electrical Characteristics[†] - Divided Clock Mode Output Timing

	Characteristic	Sym.	Min.	Max.	Units
1	CKo0 to CKo1 (8.192 MHz) delay	t _{C1D}	-1	2	ns
2	CKo0 to CKo2 (16.384 MHz) delay	t _{C2D}	-1	3	ns
3	CKo0 to CKo3 (16.384 MHz/8.192 MHz/4.096 MHz) delay	t _{C3D}	-2	2	ns

[†] Characteristics are over recommended operating conditions unless otherwise stated.

AC Electrical Characteristics[†] - Multiplied Clock Mode Output Timing

	Characteristic	Sym.	Min.	Max.	Units
1	CKo0 to CKo1 (8.192 MHz) delay	t _{C1D}	-1	2	ns
2	CKo0 to CKo2 (16.384 MHz) delay	t _{C2D}	-1	3	ns
3	CKo0 to CKo3 (32.768 MHz/16.384 MHz/8.192 MHz/4.096 MHz) delay	t _{C3D}	-1	3	ns

[†] Characteristics are over recommended operating conditions unless otherwise stated.

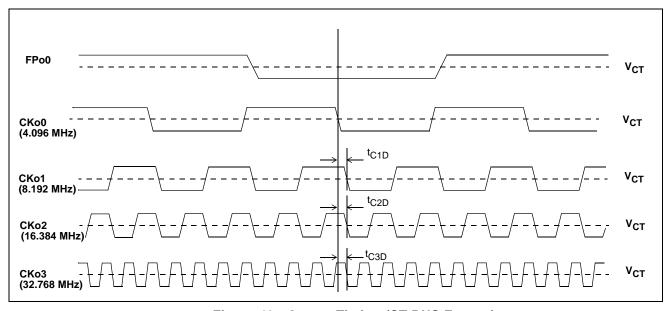
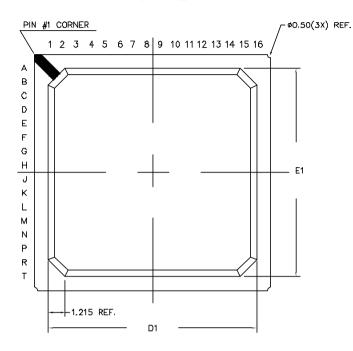
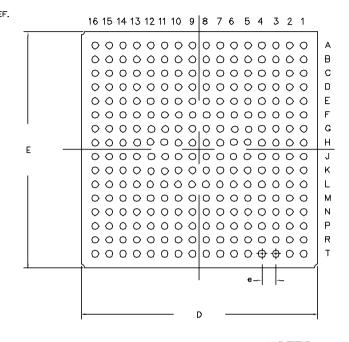


Figure 40 - Output Timing (ST-BUS Format)

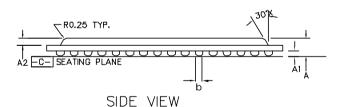
TOP VIEW

BOTTOM VIEW





DIMENSION	MIN	MAX
Α	1.42	1.80
A1	0.30	0.50
A2	0.85	REF
D	16.80	17.20
D1	14.80	15.20
E	16.80	17.20
E1	14.80	15.20
b	0.40	0.60
е	1.	00
N		56
Conform	s to JEDEC	MS-034



NOTES: -

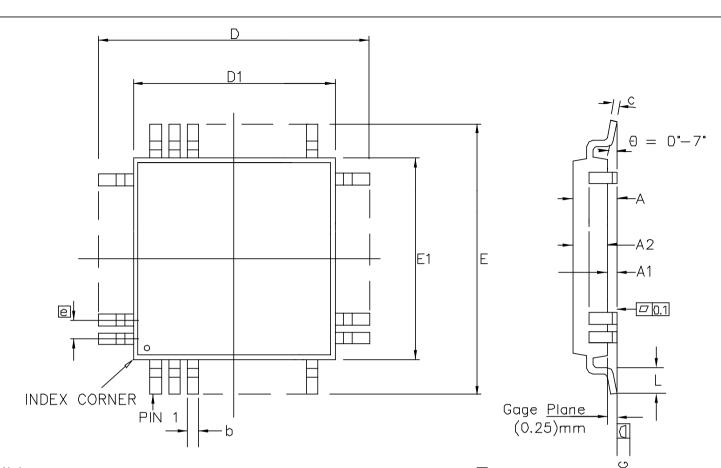
- 1. Controlling dimensions are in MM.
- 2. Seating plane is defined by the spherical crown of the solder balls.
- 3. Not to scale.
- 4. N is the number of solder balls
- 5. Substrate thickness is 0.36 MM.

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ISSUE	1							
ACN	214440							
DATE	26June03							
APPRD.								



	Fackage Code ()
Previous package codes BP/G	Package Outline for 256ball BGA 17x17x1.61mm
	GPD00842

Packago Codo



	Control D	imensions		Altern. Di	maneione
Symbol	in milli				
Symbol					ches I
	MIN	MAX		MIN	MAX
Α	_	1.60		_	0.063
A1	0.05	0.15		0.002	0.006
A2	1.35	1.45		0.053	0.057
D	30.00	BSC		1.181	BSC
D1	28.00	BSC		1.102	BSC
E	30.00	30.00 BSC 1.18			BSC
E1	28.00	BSC		1,102	BSC
L	0.45	0.75		0.018	0.029
е	0.40	BSC		0.016	BSC
b	٥.13	0.23		0.005	0.009
С	0.09	0.20		0.003	0.008
		Pin	feat	ures	
N	256				
ND	64				
NE	64				
NOTE		SQL	JARE		

Conforms to JEDEC MS-026 BJC Iss. D

Notes:

- 1. Pin 1 indicator may be a corner chamfer, dot or both, located within a zone of dimension $E1/4 \times D1/4$ from the index corner
- 2. All dimensioning and tolerancing conform to ANSI Y14.5—1982.
- 3. Dimensions D1 and E1 do not include mold protrusion allowable mold protrusion is 0.254 mm on D1 and E1 dimensions.
- 4. "N" is the total number of terminals
- 5. Package top dimensions are smaller than bottom dimensions and top of package will not overhang bottom of package
- 6. Dimension b does not include Dambar protrusion.
- 7. Controlling Dimensions are in Millimeter
- 8. At is defined as the distance from the seating plane to the lowest point of the package body

© Zarlink S	Semiconductor 2	003 All rights re	eserved.		ZARLINK SEMICONDUCTOR		Package Code
ISSUE	1	2	3	4		Previous package codes	Package Outline for 256 lead
ACN	214172	214382					LQFP (28 x 28 x 1.4mm) 2.0mm Footprint
DATE	27Mar03	12June03					
APPRD.							GPD0083/



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